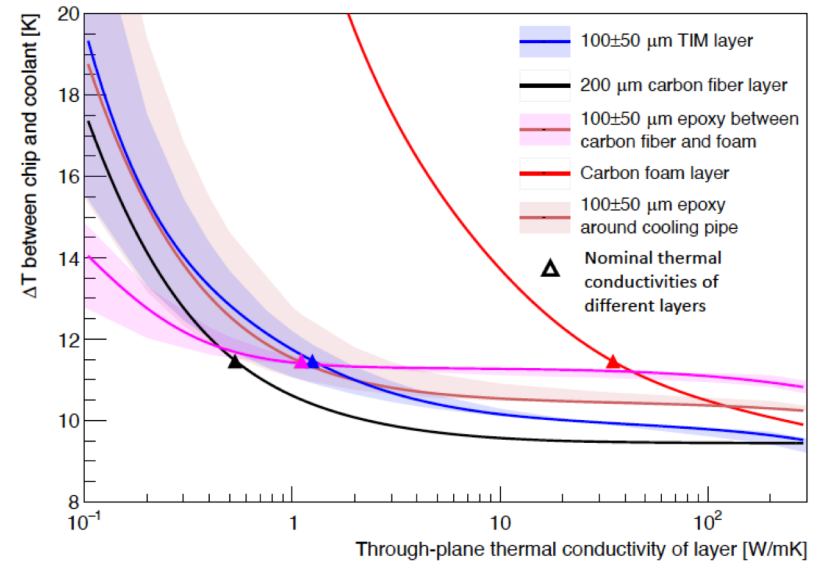


Light-weight minimal mass tracking detectors: active & passive

- The need
- Current activities & Future R&D
- Conclusions



Andy Jung

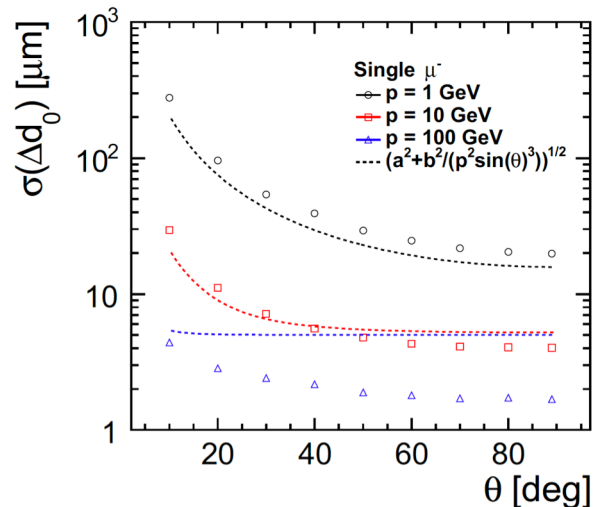
Purdue team members: E. B. Vaca, S. Karmarkar and
UG students: Ben Pulver, Ian Holda, Morgan Shoop

BNL Seminar

My own biased view

The challenge...

- ee experiment target track p_T and impact parameter resolutions of $\approx 1/5$ LHC
 - $\sigma(p_T)/p_T^2 \approx 3 \times 10^{-5} \text{ GeV}^{-1}$ ($p \leq 100 \text{ GeV}$)
 - $\sigma(d_0)/d_0 \approx 2 / 3\text{-}5 / 10 - 20 \mu\text{m}$ ($100/10/1 \text{ GeV}$ at 90°)
- R&D challenge
 - $\approx 3 \mu\text{m}$ hit resolution with $\approx 0.2 \%$ X_0 per layer (low multiple scattering) in pixel vertex detector
 - Low power (no power pulsing); readout electronics integrate over $< O(1 \mu\text{s})$
 - New paradigm for stability/alignment/calibration due to immense statistics
- Starting point concepts: CLD and IDEA
 - Typical quoted performance numbers for impact parameter resolution:



Impact parameter resolution:

$$\sigma_{d_0} = a \oplus \frac{b}{p \sin^{3/2} \theta}$$

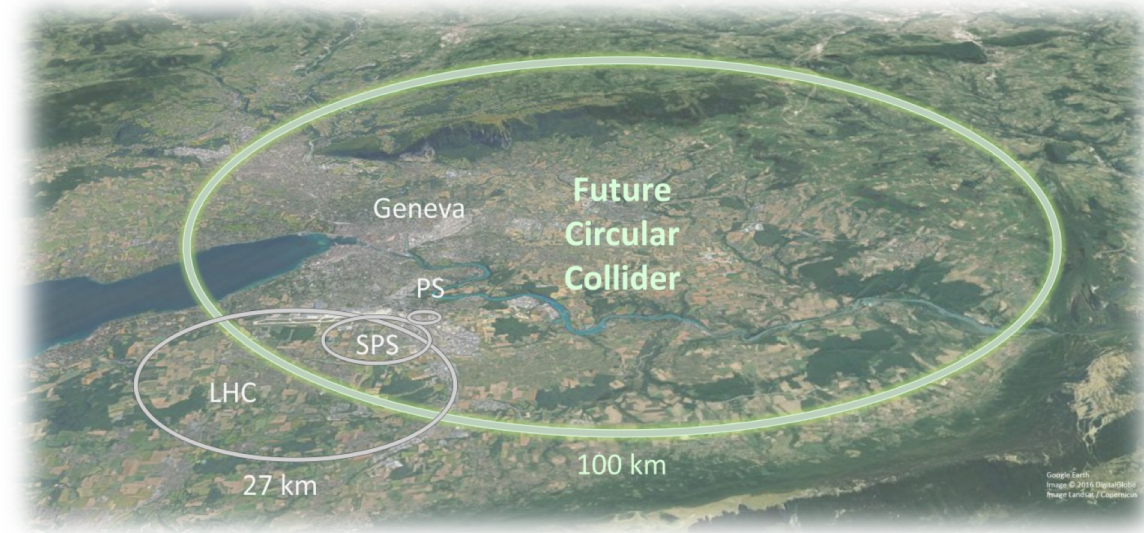
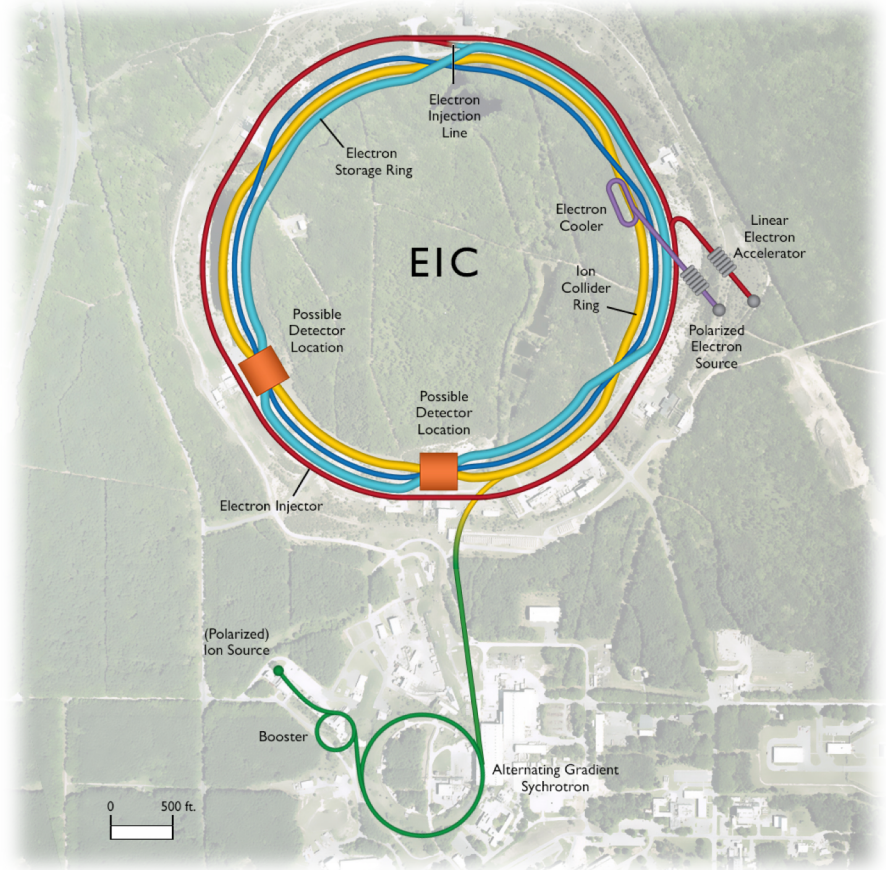
CLD: $a \approx 2 \mu\text{m}$; $b \approx 20 \mu\text{m}$

IDEA: $a \approx 2 \mu\text{m}$; $b \approx 15 \mu\text{m}$

ILD: $a \approx 5 \mu\text{m}$; $b \approx 15 \mu\text{m}$

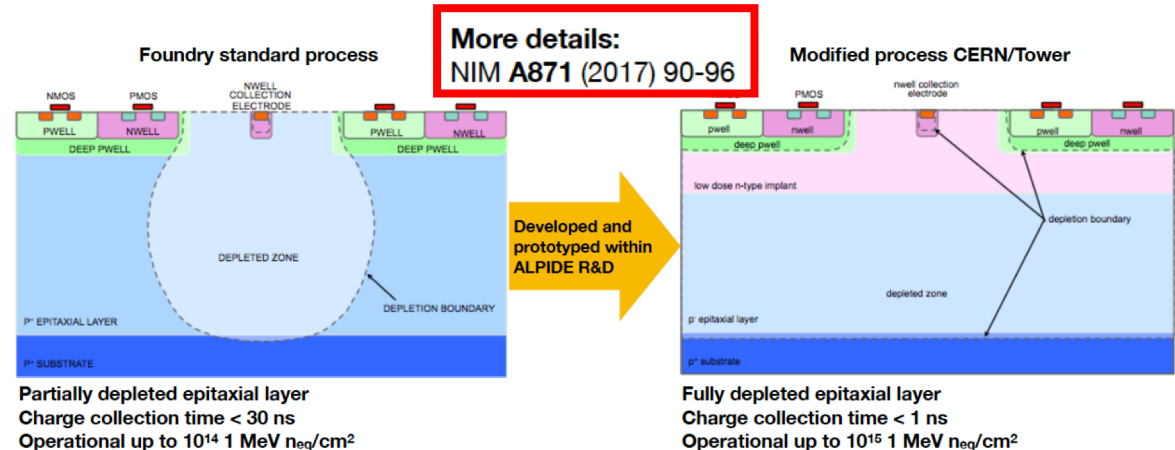
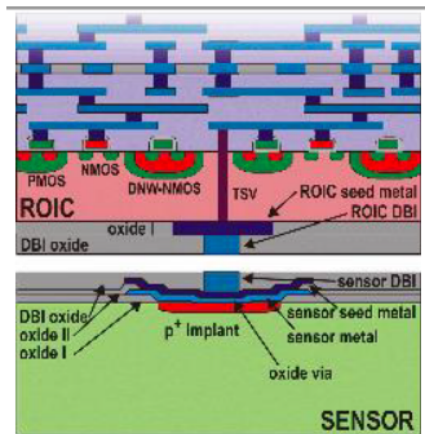
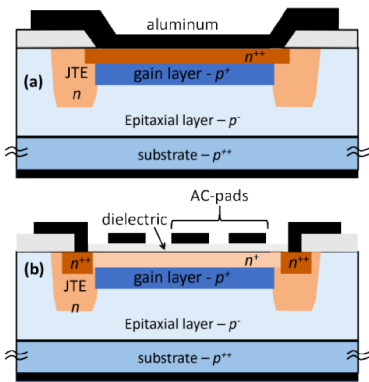
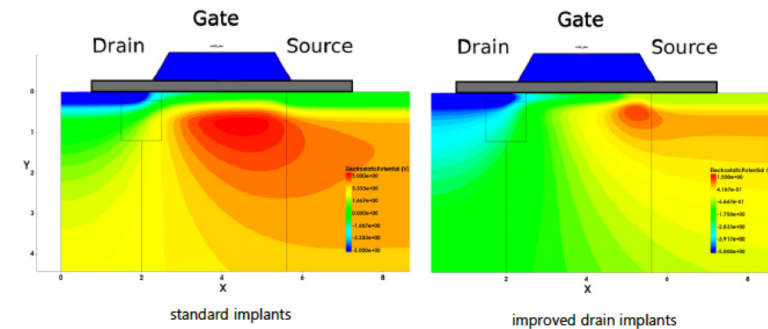
Many avenues possible

- Low mass detectors
- Low mass structures
- Dual use structures
- ...



Strong ties to Foundries, allows...

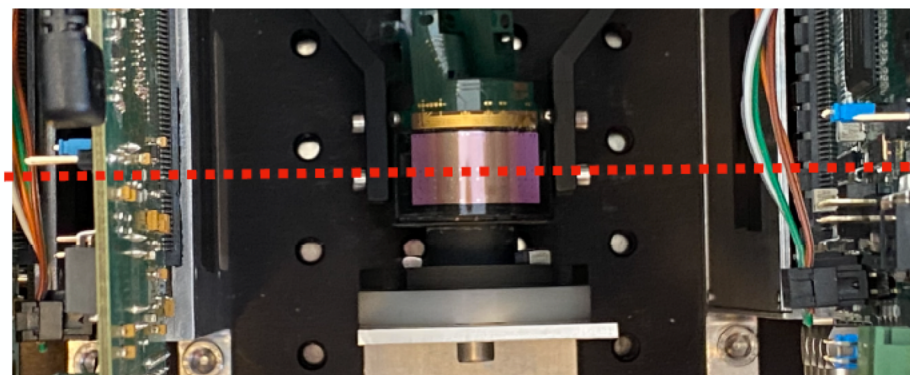
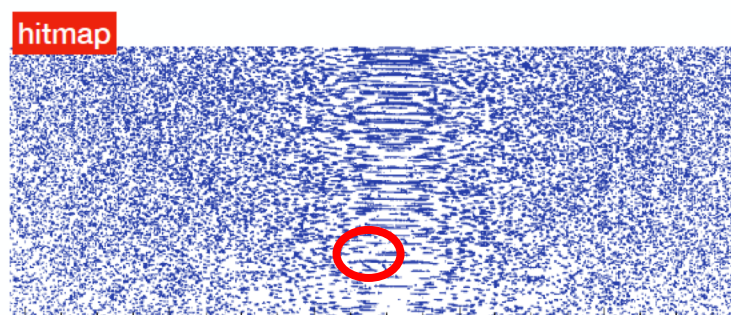
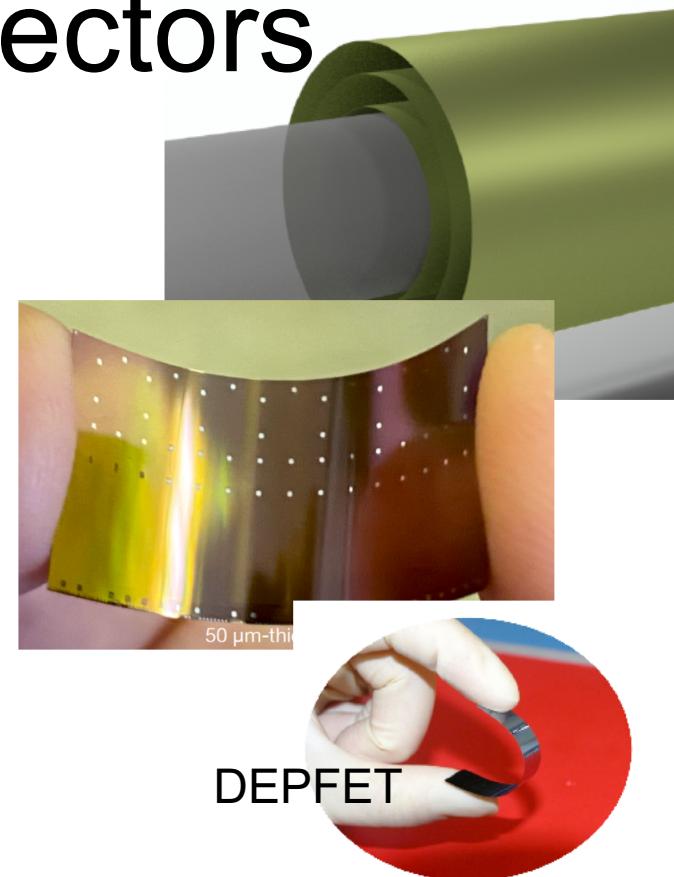
- Manipulation of the CMOS process to boost technology
 - Uniform epitaxial layers → speed & radiation hardness
 - Usage of larger wafers & stitching
 - 65nm technology: charge collection properties uncertain with thinner epitaxial layers
- DEPFET improvements: Better drain implants
- 3d integration (not 3D technology)
- LGADs and inverted LGADs
 - Smaller pixel possible but lots of power for time resolution → cooling ? mass ?



19 Gabriele Giacomini et al

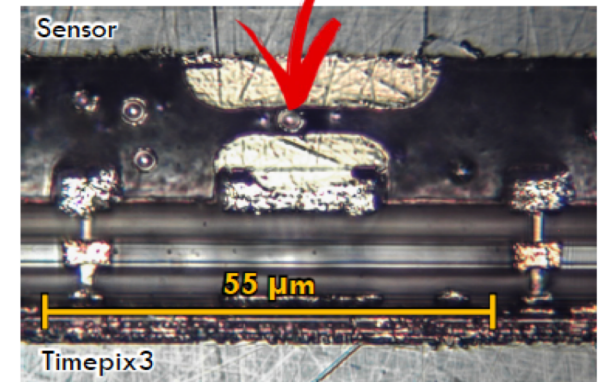
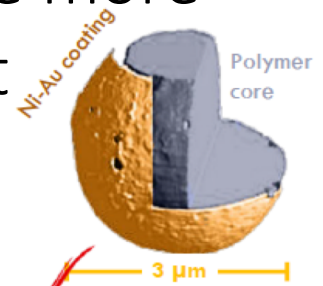
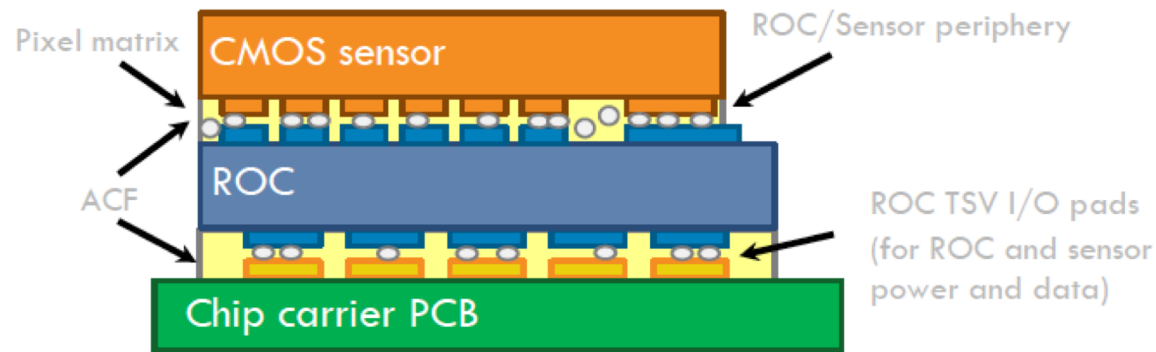
Very thin silicon detectors

- Bent ALPIDE (M. Mager) and the “golden detector” (ITS3)
- ALPIDE: amazing test beam results
 - Challenges remain, bending influences electric parameter
- DEPFETs are also bendable (L. Andricek)
- Allows very minimalistic support structures, i.e. almost “none”
- EPIC applications...



Hybridization

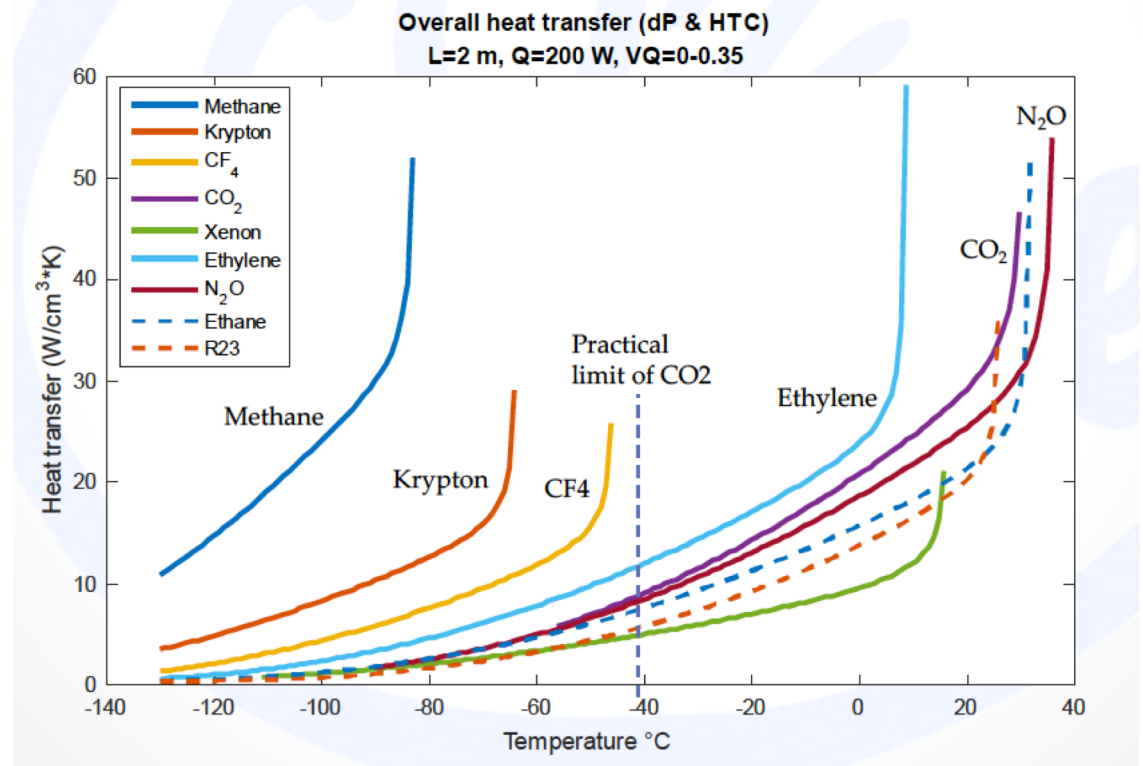
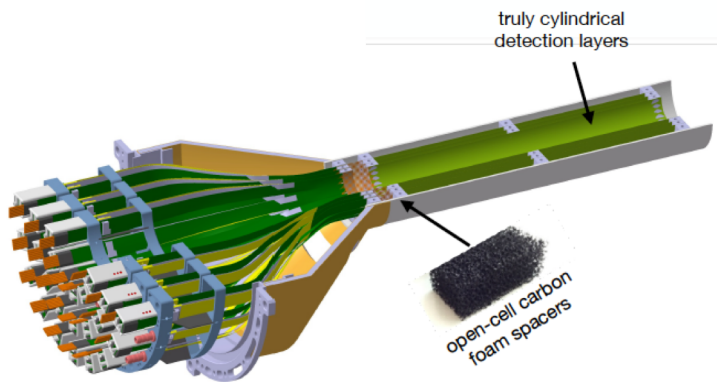
- While MAPS/CMOS is perfect for innermost layers, the more “classic” hybrid detectors still an option for outermost
 - Bonding forces doable, but yield remains low for now
 - Very small bond layers, almost like 3D integration...



- Can this technology be a solution for interconnecting the ends of ALPIDE ladders?

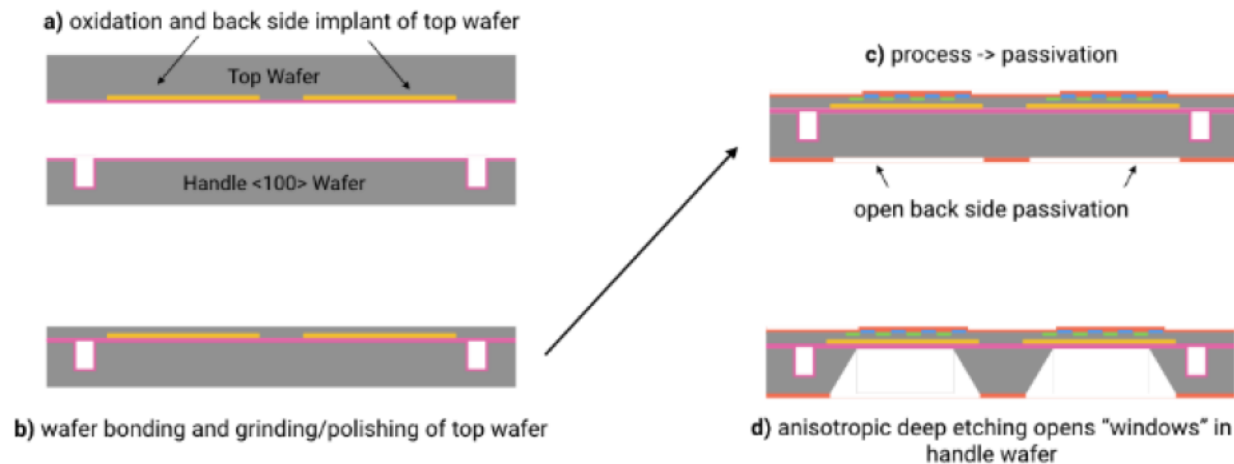
Cooling & support structures

- Reached the limit for cold CO₂ technology
- Further improvement if power densities require it:
 - Super-critical krypton cooling (around -60C)
- ...but air cooling the “weapon of choice” as long as power densities are low enough
- Little to no support mass needed, example ALICE ITS3
- Can we dream ? 1st layer of vertex detector into beam pipe
- Beam current shield vs. beam pipe mass



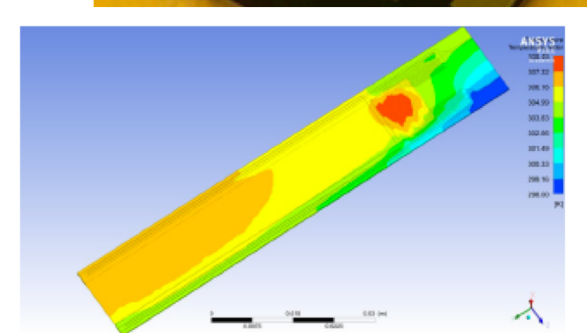
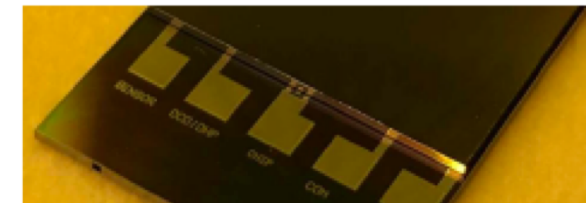
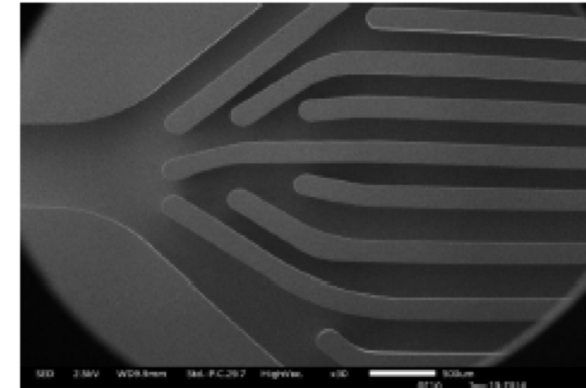
Micro-channel cooling

- Microchannel cooling is established to perform as expected by LHCb, now possible to consider for others



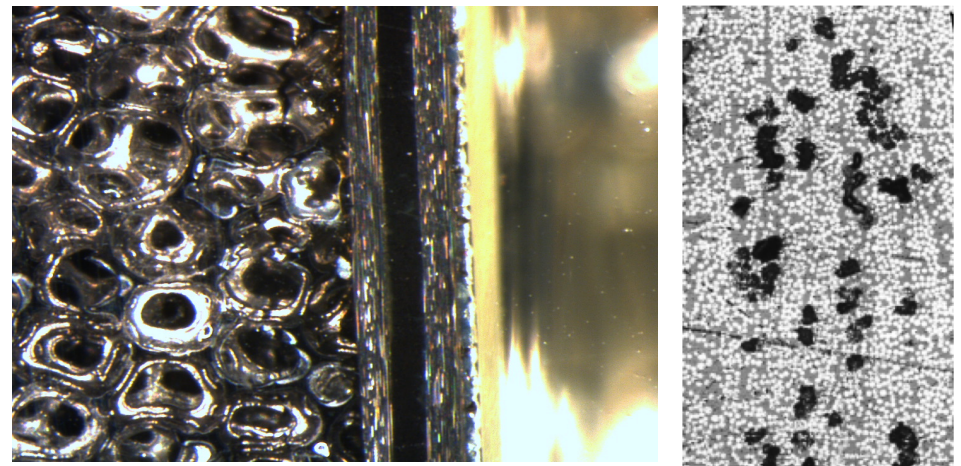
Cavity SOI process: can be adapted to any traditional silicon detector

Silicon on insulator (SOI) technology is fabrication of silicon semiconductor devices in a layered silicon-insulator-silicon



What about supports ?

- Carbon Fiber is THE material of choice for structures
- Highly thermally conductive
- Extremely strong, e.g. support 10x self-weight
 - 500kg structure for 5 tons (CMS BTST)
 - 3 kg structure for 30 kg pixel detector
 - Minimal mass



Future colliders (FCC like)

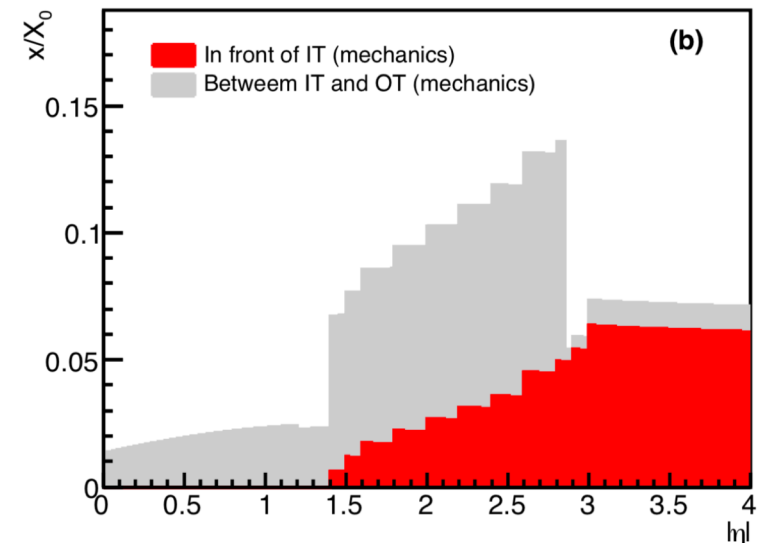
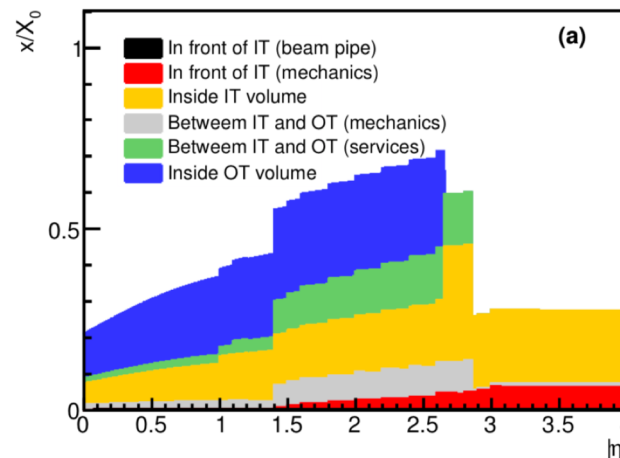
High-luminosity phase of the LHC as example in this talk, but future colliders

- Larger angular coverages extend into forward directions
- Challenging for forward tracking/detectors
- Pile-up of a thousand results in very harsh conditions (@FCC-hh)

| Pixel Layer dose (3.7cm) | HL-LHC $3ab^{-1}$ | FCC $3ab^{-1}$ | FCC $30ab^{-1}$ | FCC (2.5cm) $30ab^{-1}$ |
|---------------------------------|----------------------|-------------------|--------------------|----------------------------|
| $\times 10^{16} n_{eq} cm^{-2}$ | 1.5 | 3 | 30 | 70 |
| Dose (MGy) | 5 | 10 | 100 | 220 |

Example of the HL-LHC upgrades as example:

- Support structures need to be optimized, light-weight \rightarrow minimal mass possible, highly thermally conductive
- CMS HL-LHC upgrades as example

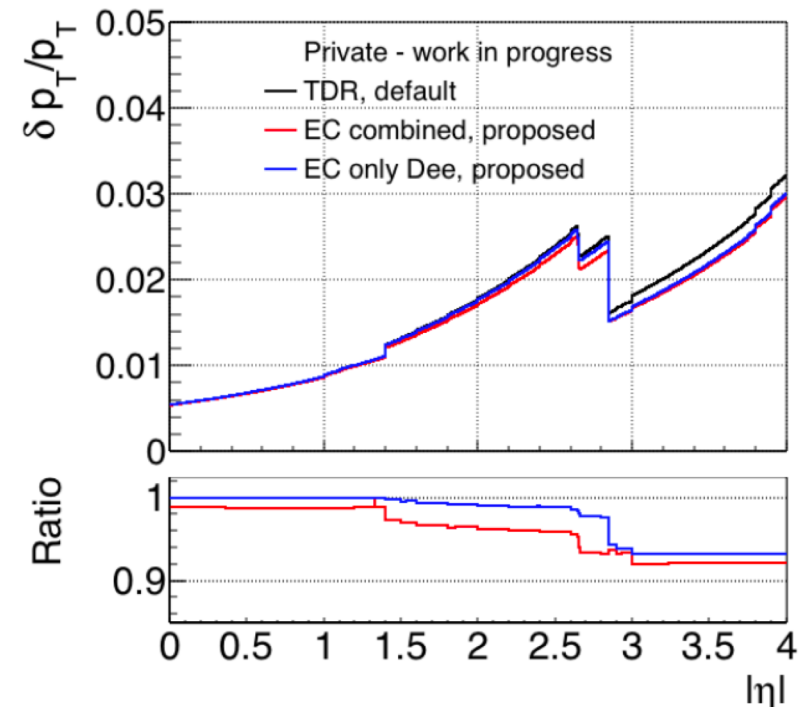
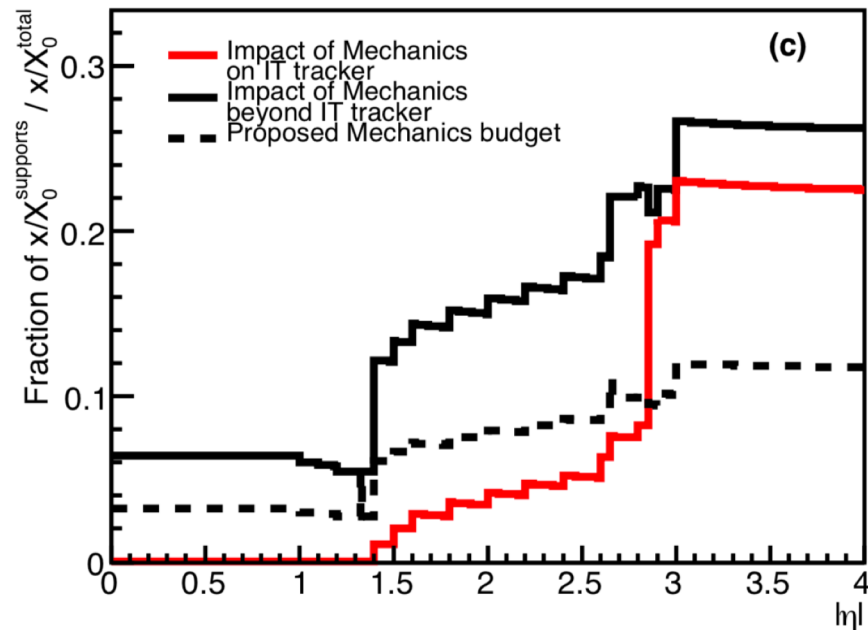


Material budgets & mechanics

Substantial R&D on all fronts to make a FCC-hh detector a reality

- Support & Cooling constrains Tracker performance, e.g. thermal runaway
- Mechanics is significant fraction of the material budget
- **Lowest mass possible requires new approaches to an old topic**

Fraction of mechanics vs entire Detector material



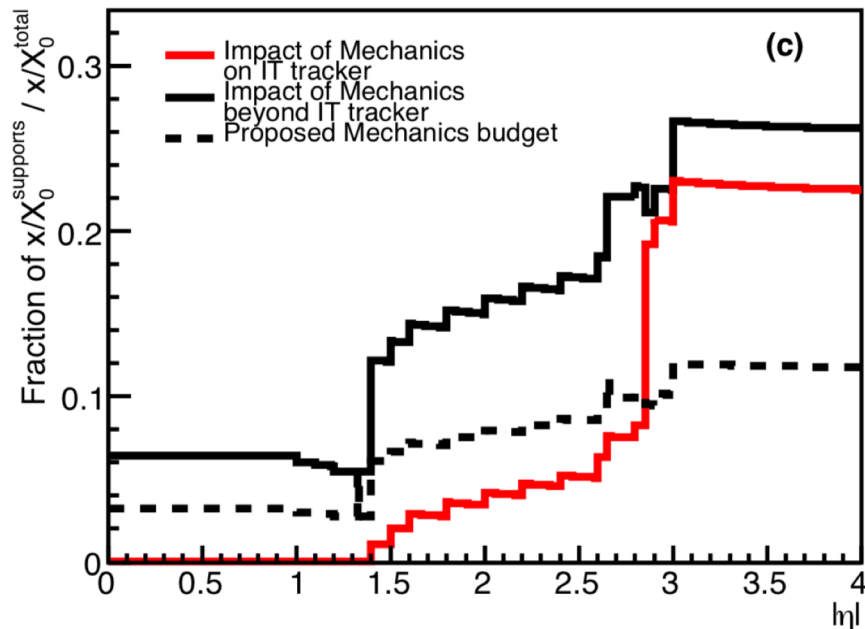
- Can improve b-ID efficiencies by $\sim 2\%$ per b-jet and high b-jet multiplicity $\sim 10\%$
- Significant improvement by novel approach, b-ID relevant for top & Higgs physics

Material budgets & mechanics

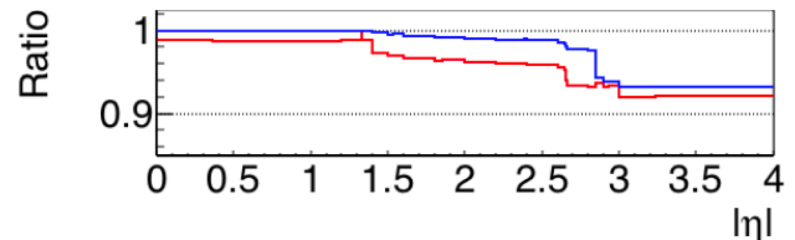
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Fraction of mechanics vs entire Detector material



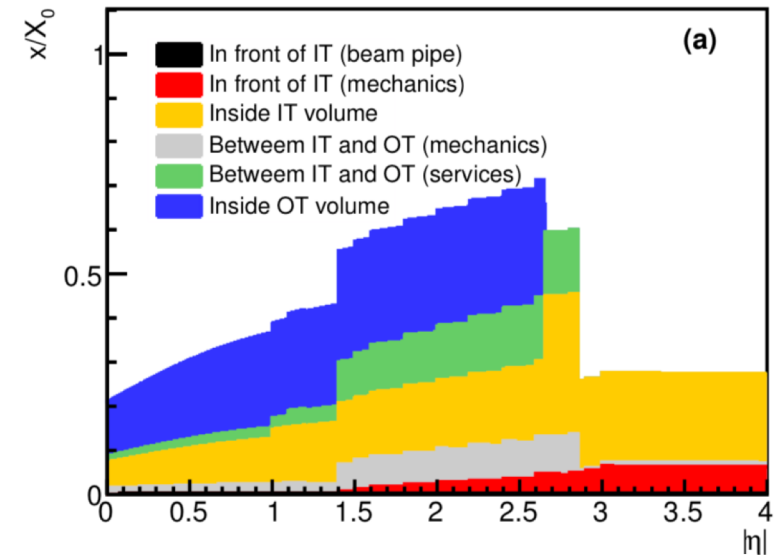
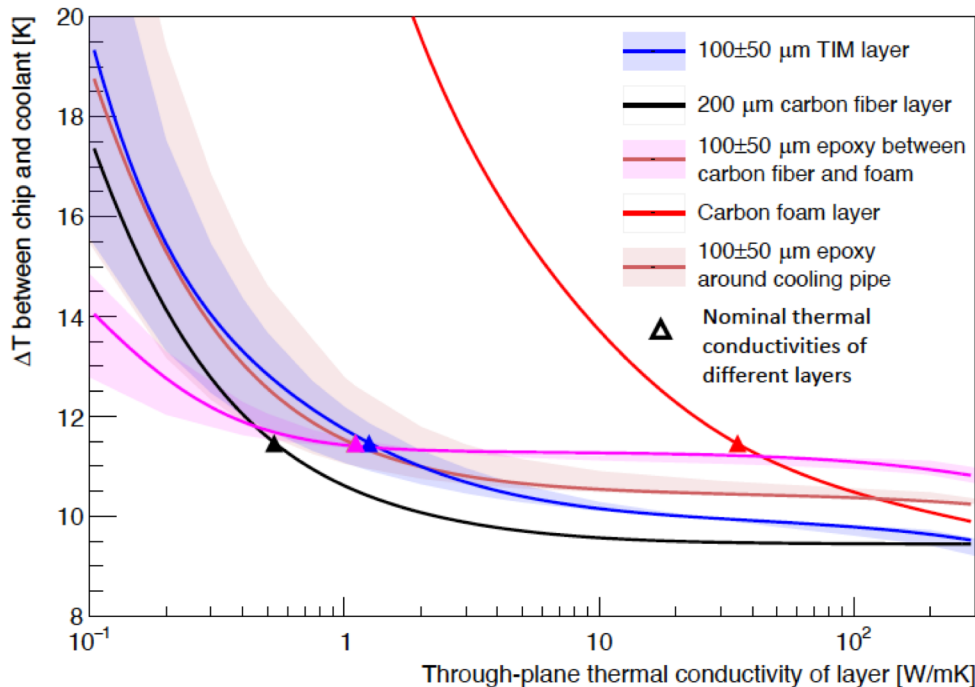
Are we harvesting all physics and performance out of great instruments to unravel mysteries of nature ?



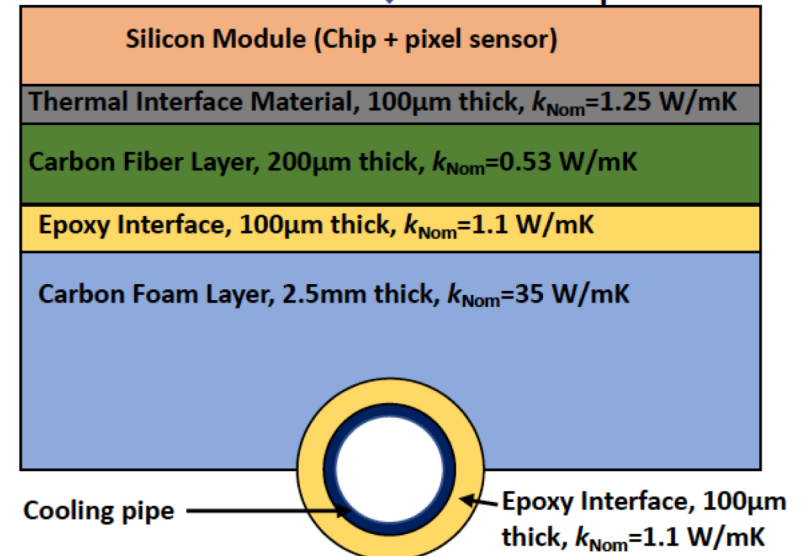
- Can improve b-ID efficiencies by $\sim 2\%$ per b-jet and high b-jet multiplicity $\sim 10\%$
- Significant improvement by novel approach, b-ID relevant for top & Higgs physics

Tracker of the HL-LHC is a very significant fraction of the total CMS upgrade budget

- Support & Cooling is the constrain in which Tracker is operated, e.g. thermal runaway
- Mechanics is sizeable fraction of the material budget
- Requires detailed FEA & mock-up's to understand and verify experimental measurements



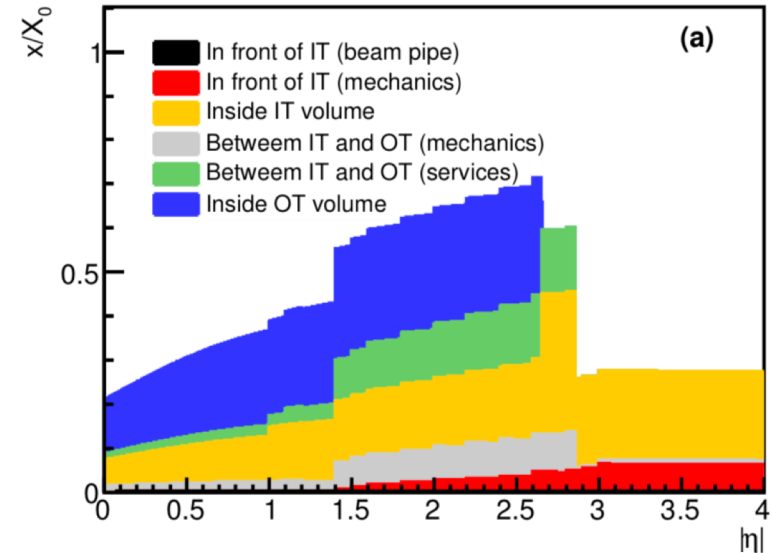
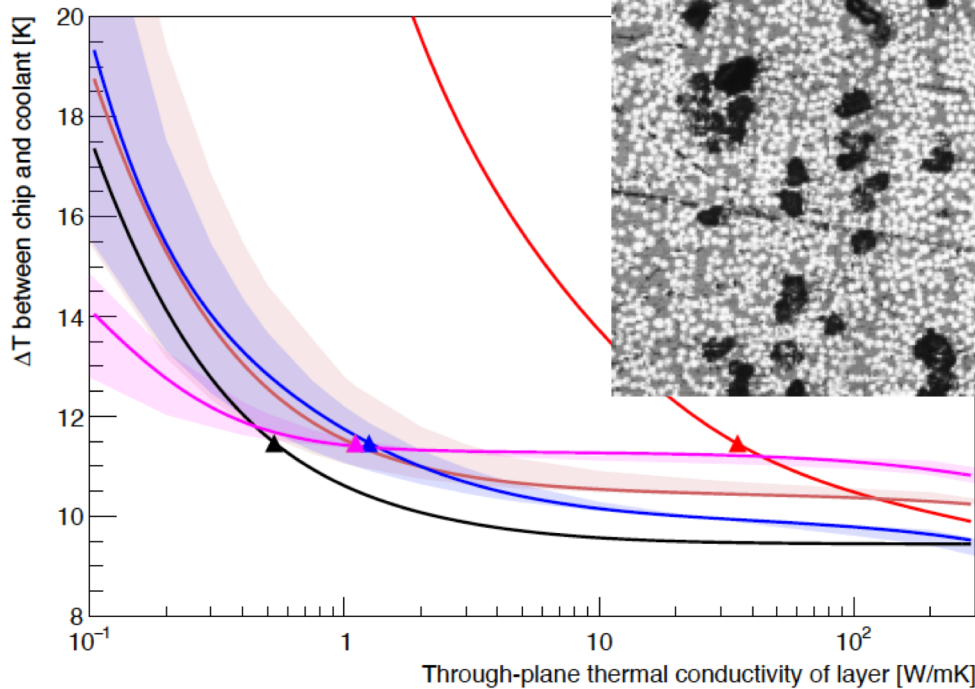
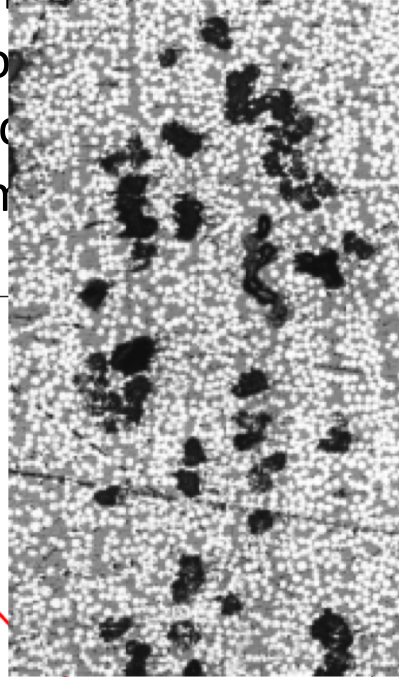
Heat generated by different components



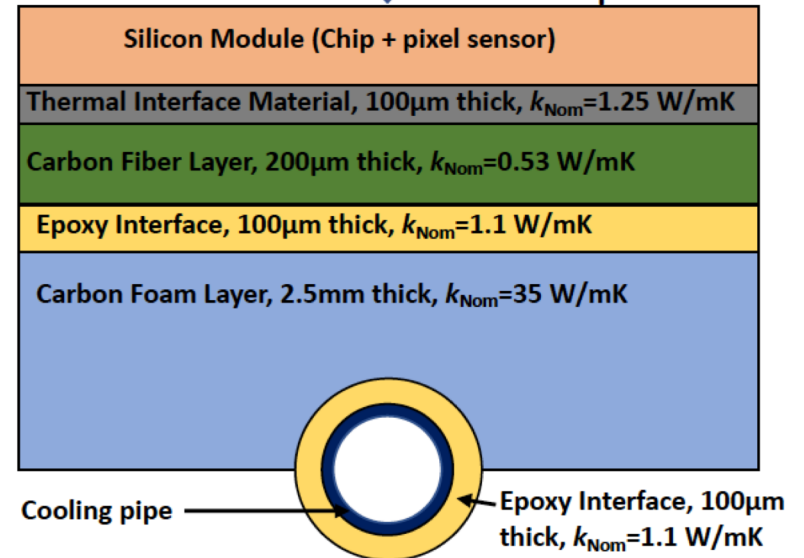
Impact of tracker mechanics...

Tracker of the HL-LHC is a very significant fraction of the total CMS upgrade budget

- Support & Cooling is the constrain in which Tracker is operated, e.g. thermal runaway
- Mechanics is sizeable fraction of budget
- Requires detailed FEA & modeling and verify experimental results



Heat generated by different components

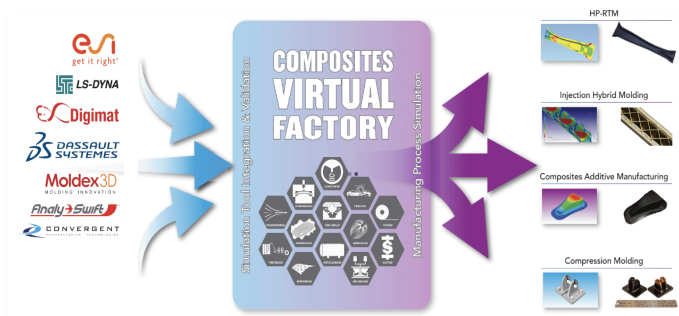


Completed in summer 2016:

- Composite manufacturing & simulation center (CMSC)
- Multi-disciplinary center: Aeronautics, Chemical E, Materials E, Aviation Tech, Computer graphics

A Purdue Center of Excellence:

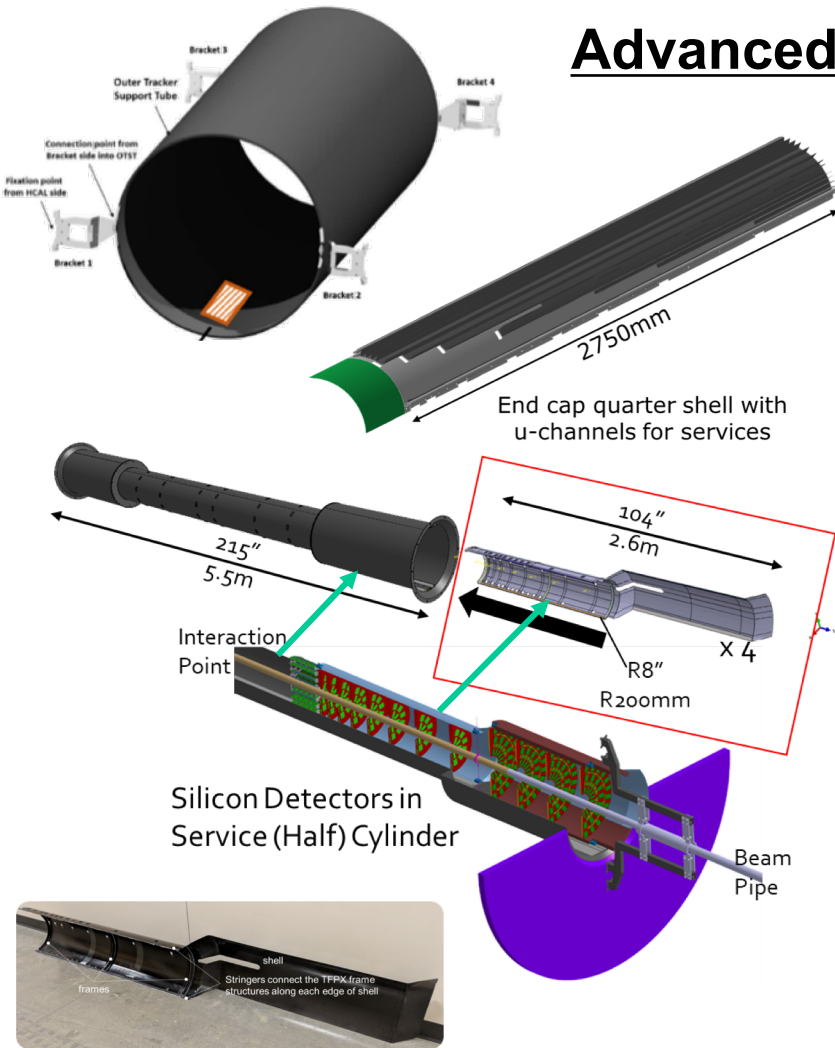
- Experts in simulation as a decision-making tool for composites
- Dassault Systems Simulation Center of Excellence
- Process-specific engineering workflows



Supporting technologies

- Technical cost modeling
- Big data - AI

Advanced Mechanics & Composites activities at Purdue



Large Support Structures – light-weight but rigid

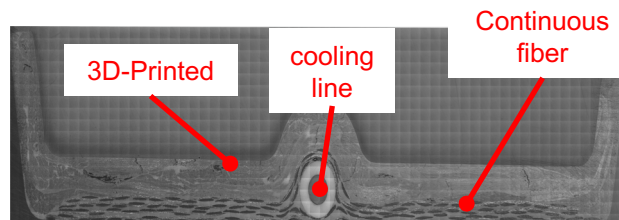
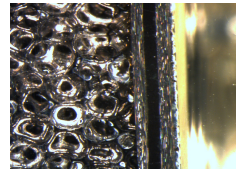
1. [BTL Tracker Support Tube \(CMS\)](#)
2. Inner Tracker Support Tube (CMS)
3. Inner Tracker Service Cylinder (CMS)
4. End Cap Quarter-Shells (ATLAS)

Small Structures – extremely flat and thin

1. Pixel Dees Support Structure (CMS)
2. High-TC flat sheets for silicon modules (CMS)

Irradiation campaigns:

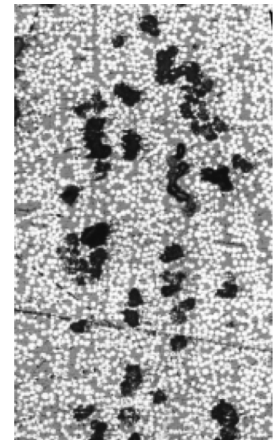
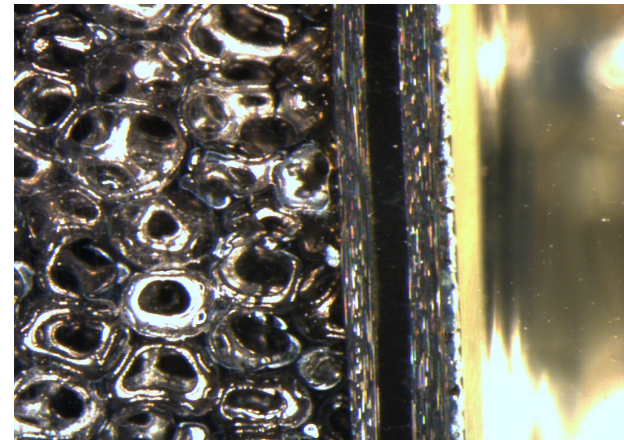
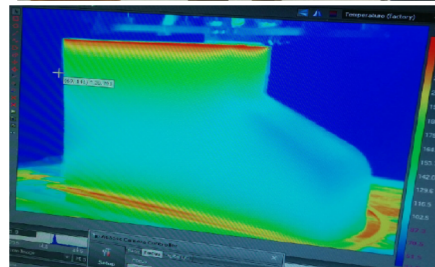
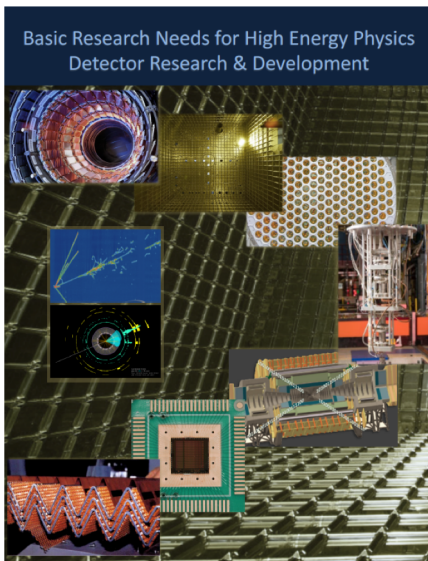
- In collaboration with US TFPX institutes (Cornell, Rice, others)



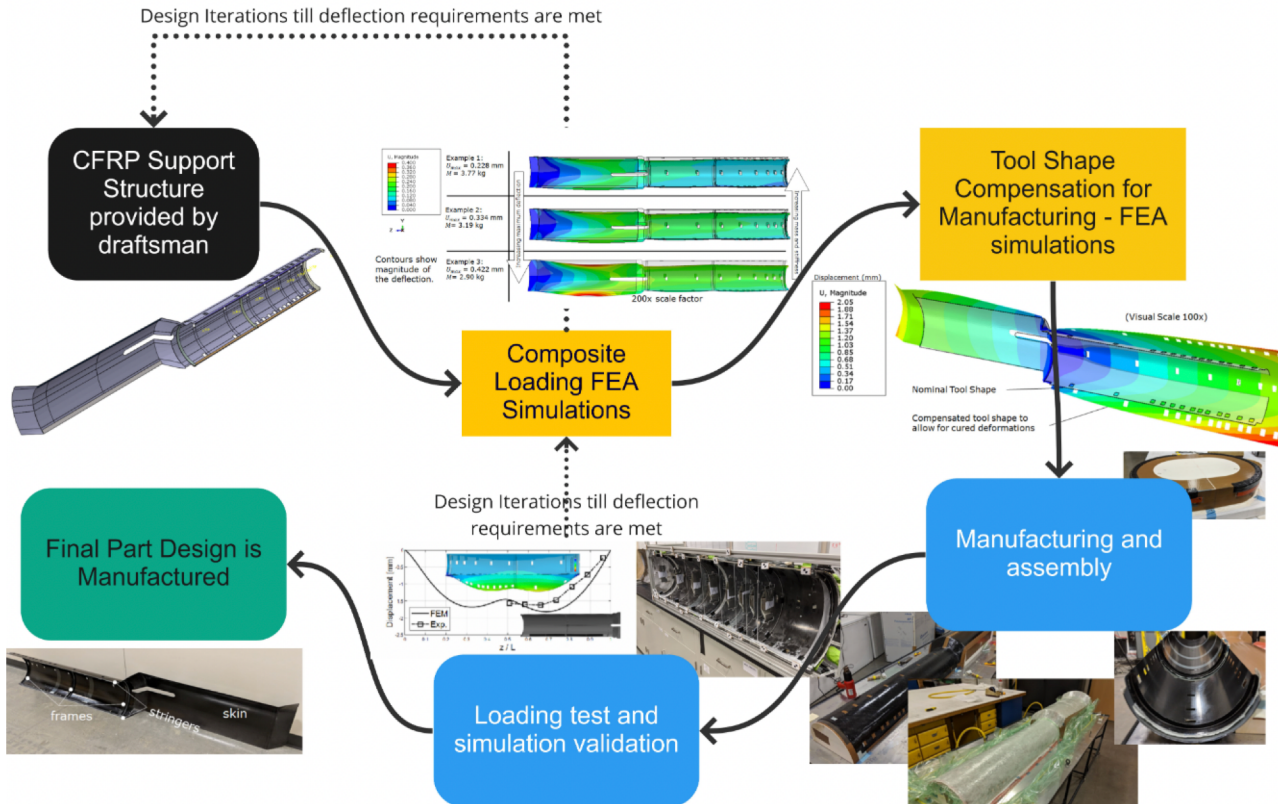
Future Mechanics and R&D:

1. “BlueSky Mechanics” for detectors at future Colliders (FCC, muon, LC, etc.) <https://arxiv.org/abs/2203.14347>
2. “CalVision” project for mechanics of dual readout calorimetry <https://arxiv.org/abs/2203.04312>

- R&D efforts on low-mass support structures with integrated services for silicon detector systems
- Targeting the Basic Research Needs for HEP by DOE topic of “Realize scalable irreducible-mass trackers”, thrust 2 on low mass detector system.
- Leverage current activities on high-TC, accurate predictive manufacturing of large composite structures, etc.
- Connections with companies engaged in high-TC carbon foam development
- Multi-functional composite structure research
- Integration of cooling and other services into the support structures to reduce mass further
- Novel approach to mechanics design from **inception phase of the detector**
- Need to start early/ier with R&D...



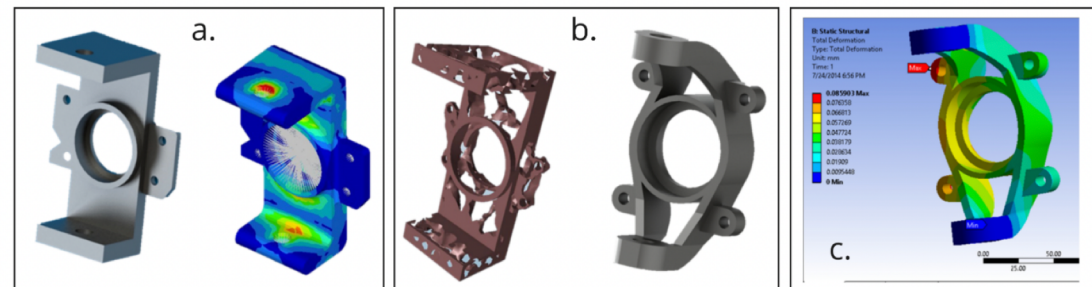
- Scalable mechanics structures: multi-functional & mass optimized
- Ease integration, applies also to calorimetry, TOF, etc.



Full cycle of Process & Performance simulation:

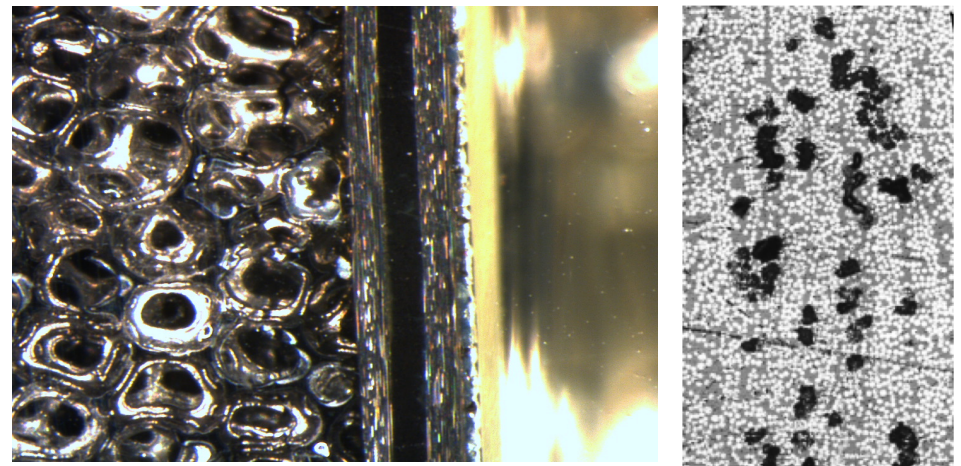
- FEA, prototypes, iterative process.
- Consistent approach to better controlled manufacturing process, eases assembly.
- Especially true the larger the structures become, integration is a “challenge”

- Collaboration with material sciences, companies for novel materials, and latest techniques.
- Example: ML for optimization with HEP inputs, **excites future generation**



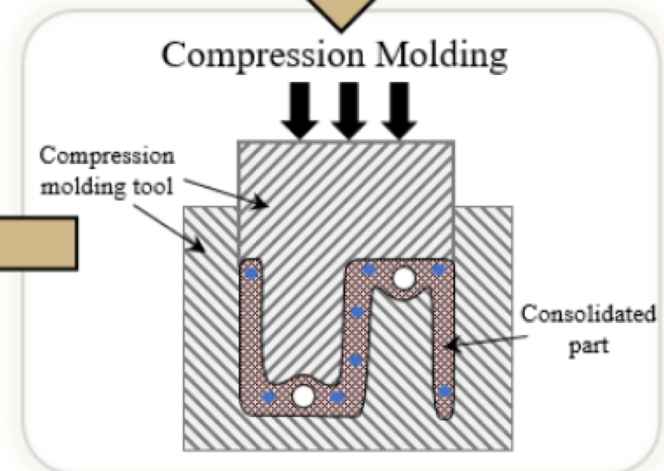
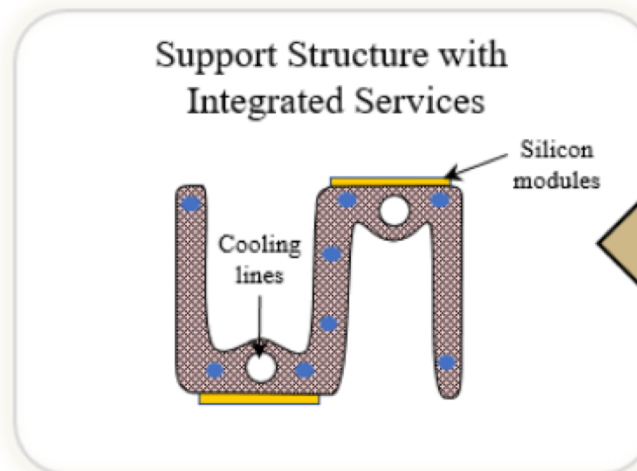
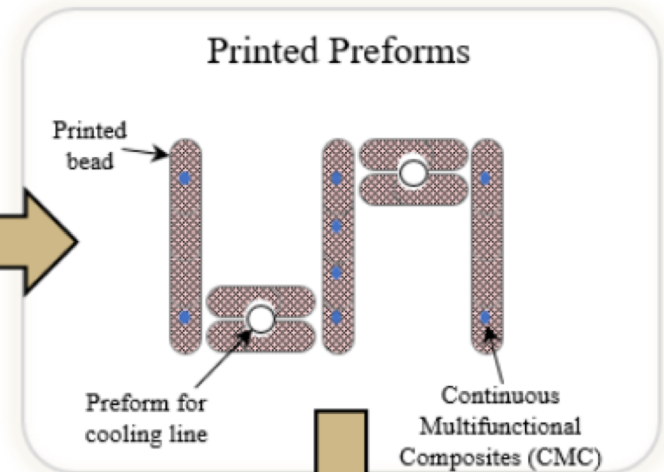
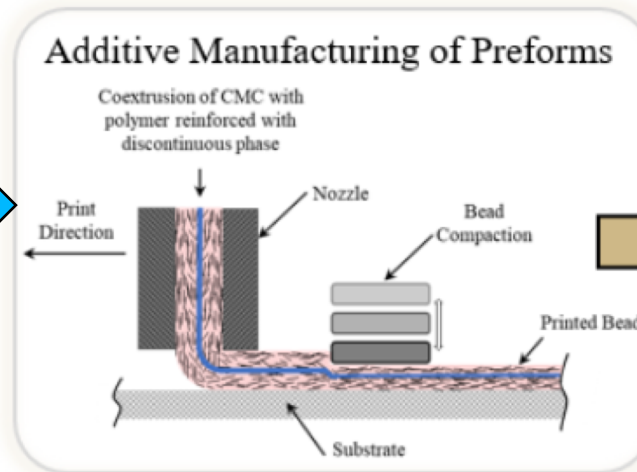
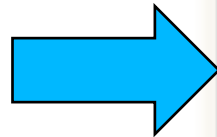
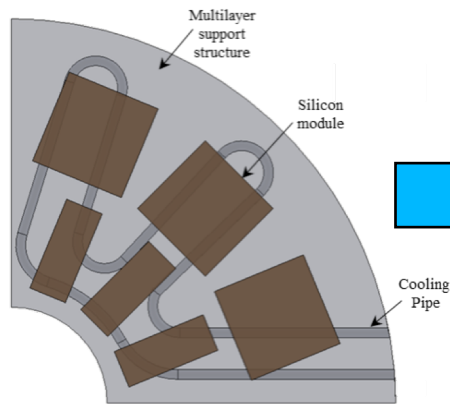
What about supports ?

- Carbon Fiber is THE material of choice for structures
- Highly thermally conductive
- Extremely strong, e.g. support 10x self-weight
 - 500kg structure for 5 tons (CMS BTST)
 - 3 kg structure for 30 kg pixel detector
 - **Minimal mass by dual-use**



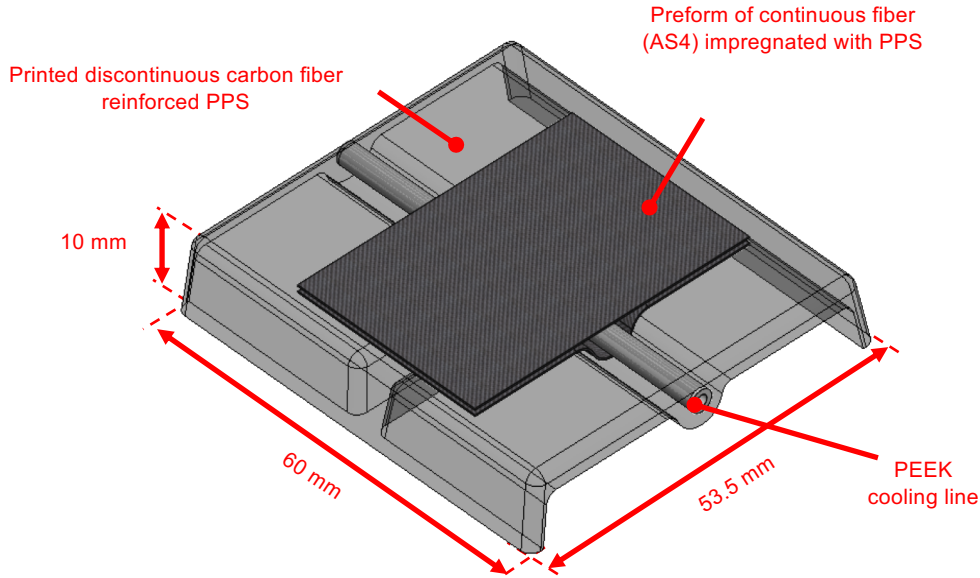
Identified by DOE BRN effort & CPAD

- Scaling of low-mass detector system towards irreducible support structures with integrated services. Includes: integrated services, power management, cooling, data flow, and multiplexing.

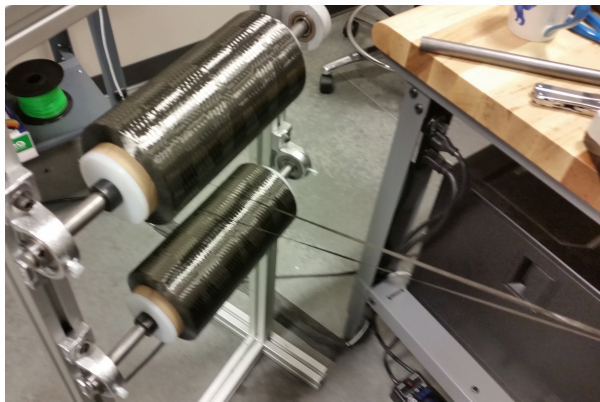
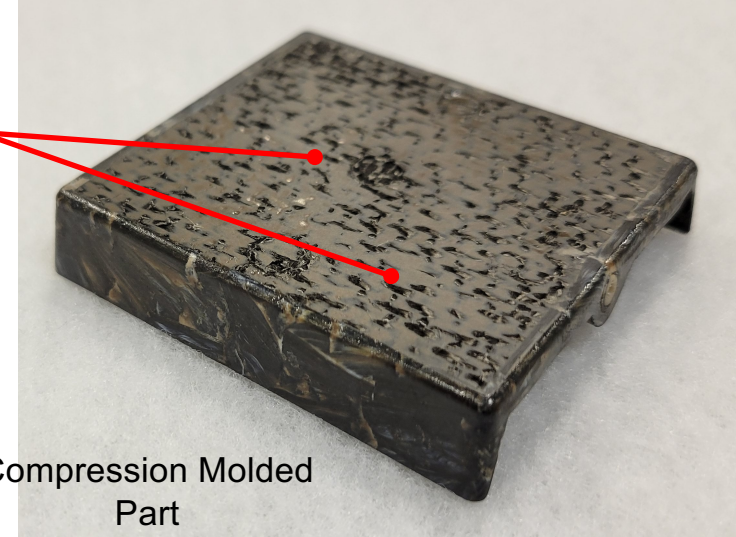


- Collaboration with material sciences, companies for novel materials, and latest techniques.
- Example: Cutting-edge composite manufacturing techniques, in-house
- **Reduce mass & boost thermal performance**

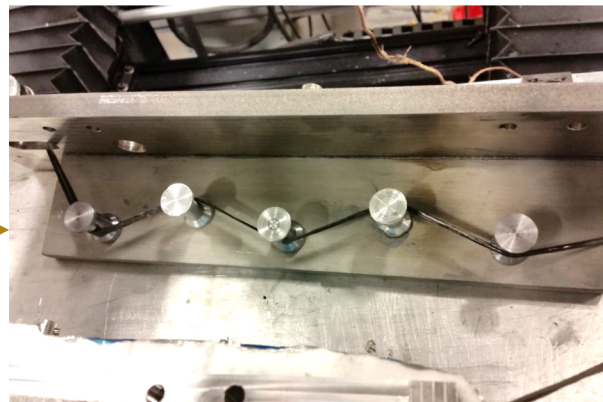
First prototypes look promising...



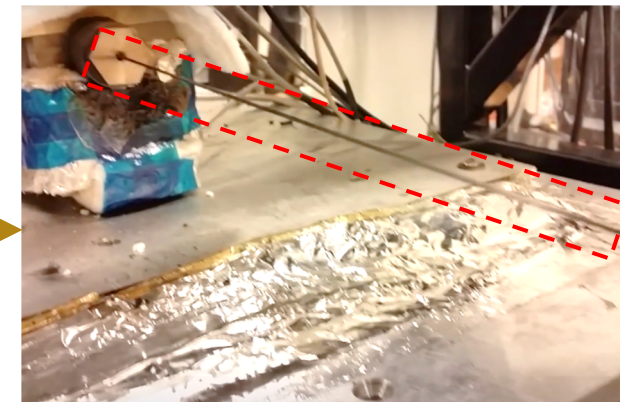
Continuous CF exposed at the surface for enhanced thermal conduction.



Spools of Carbon Fiber

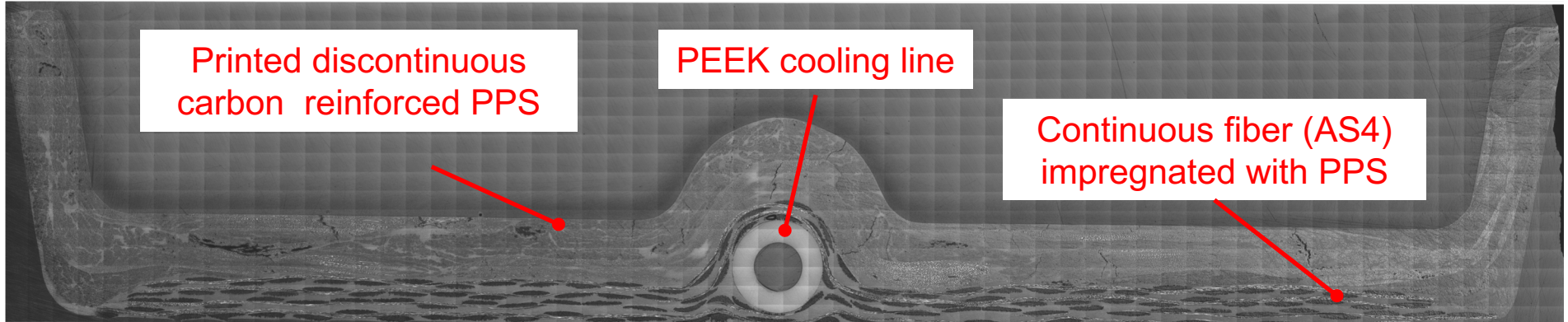


Interior of Impregnation Chamber



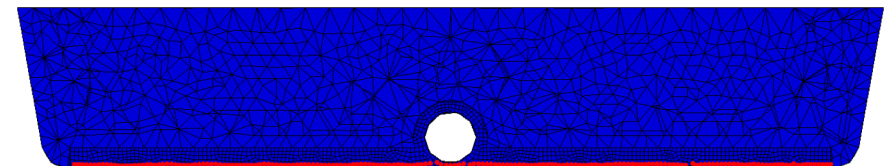
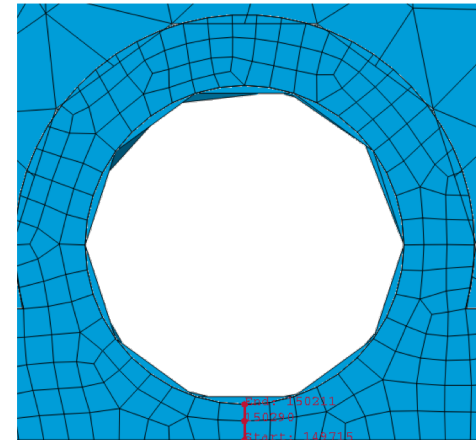
Carbon Fiber Impregnated with PPS

Cross-sectional micrograph of first prototypes



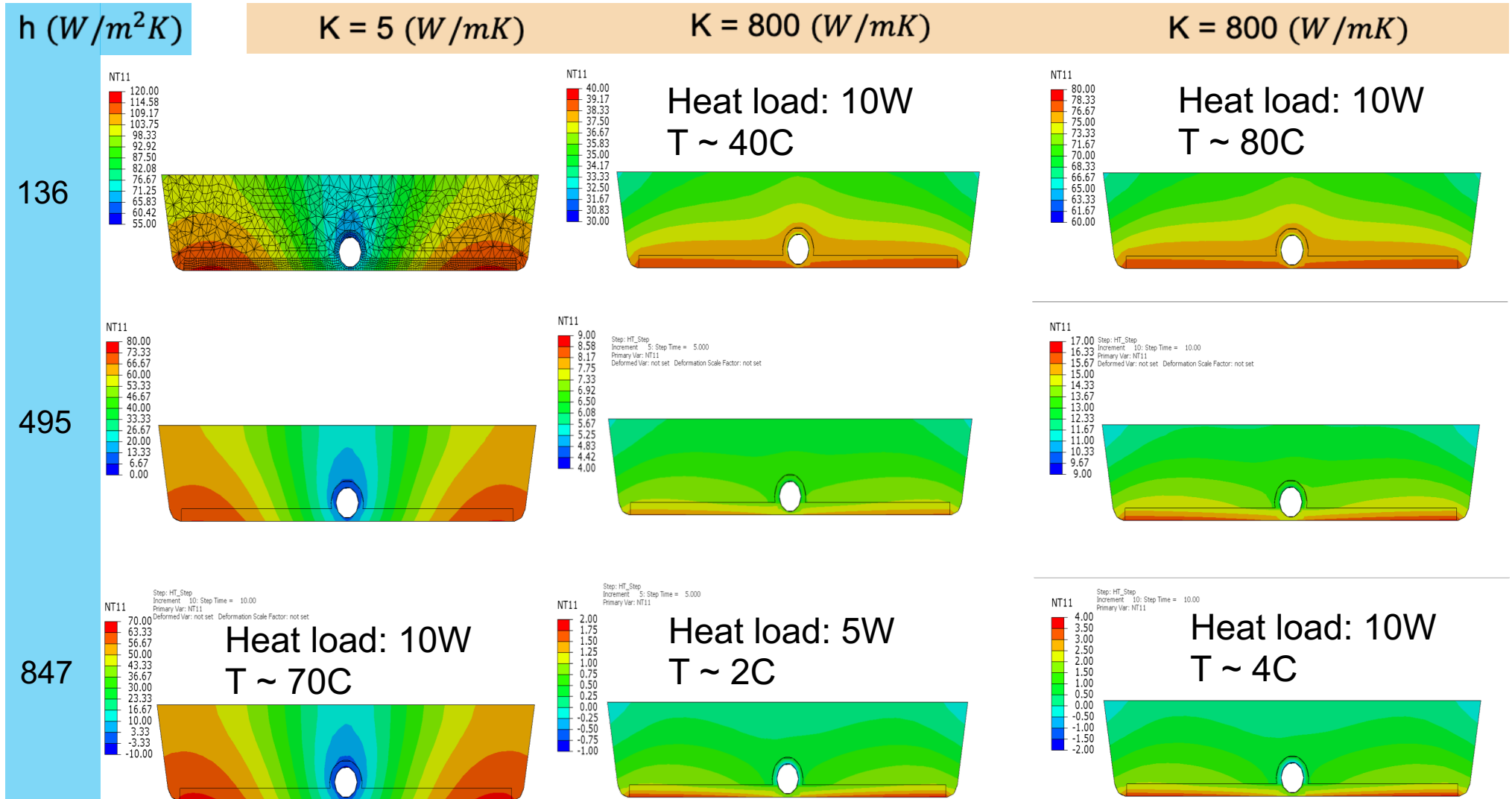
Detailed FEA studies:

- Similar conditions as for CMS HL-HLC FEAs
- For now: Modeled as an N2 turbulent flow at -20 Celsius with a constant volumetric flow
- Different scenarios for thermal transfer coefficient
- Compare results along continuous fibers and between “pipe” and surface



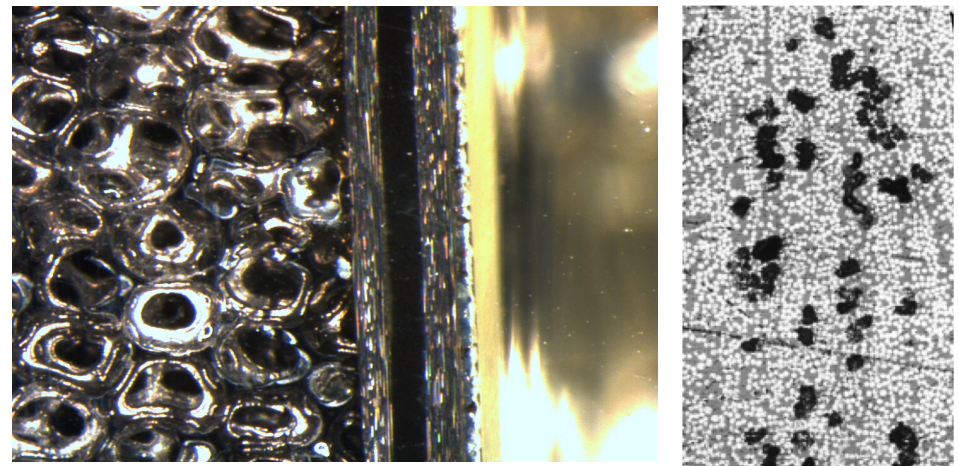
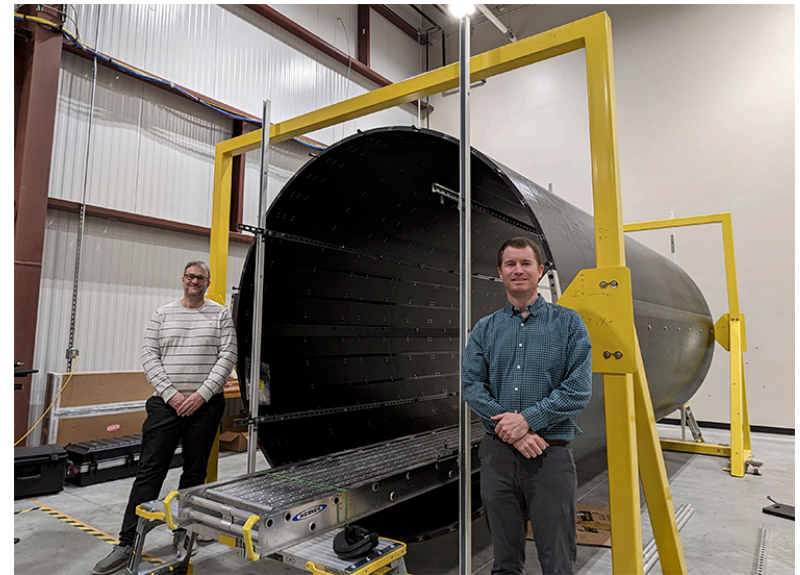
Thermal performance improved compared to state-of-the-art

- Already at a lower mass and can be further reduced...



Carbon Fiber is great material

- Can it be active...
- A Carbon Fiber wire chamber offers great prospects to save material



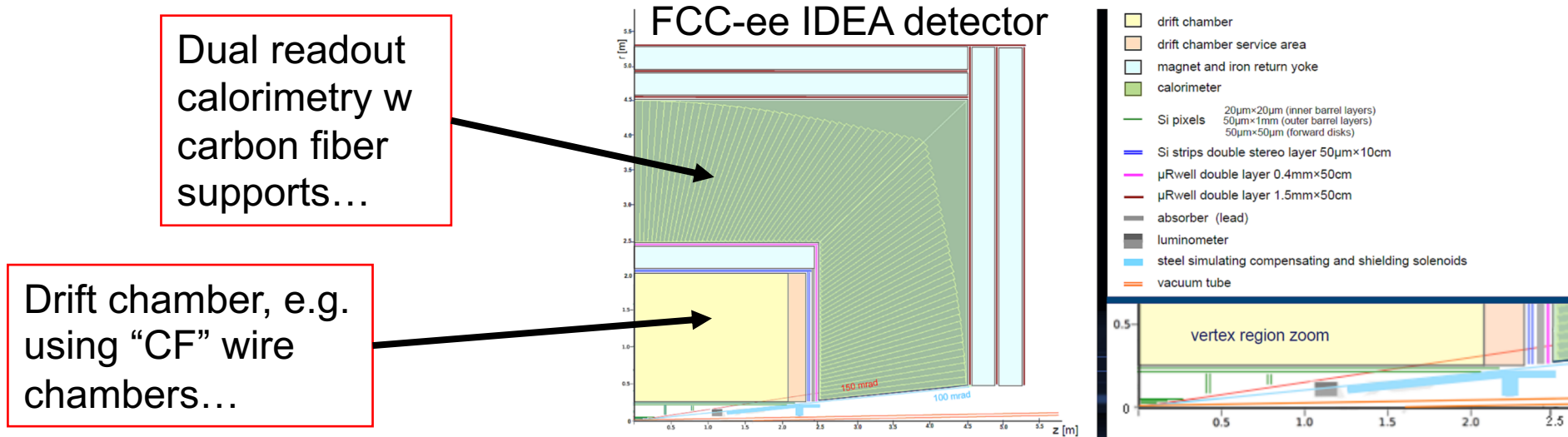


Figure 6: Cross section of the proposed layout for the IDEA detector concept.

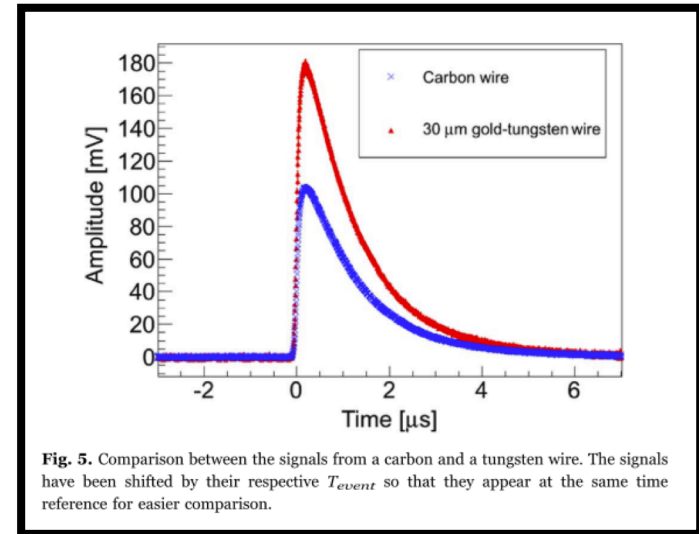
- Example of "large detector" but detector mechanics / services / cooling play a significant role in a detector's performance
- **Highly relevant also to small experiments & EIC ?!**

Exchange of ideas & progress across existing collaborations:

- "CPAD RDC 10": R&D Collaboration for "Detector Mechanics R&D"
- 9 others, so covers also your favorite topic's <https://cpad-dpf.org>
- Bridges nuclear, high energy physics but space applications / satellites too – broad field!
- Forum on tracking detector mechanics @Purdue: <https://indico.cern.ch/e/ftdm24>

- G. Charles et al. compared gold-plated tungsten wires to carbon wires for applications in multi-wire chambers
- This example: **factor 5 reduction** in material when moving from W+Al to C+Ag/Cu
- Supports also a topic
- Volume separation

[NIM A Vol 855, 2017](#)

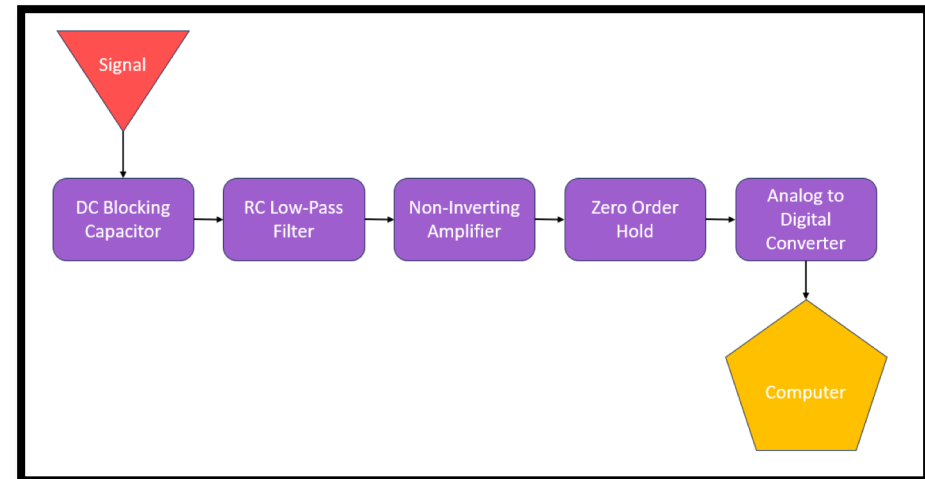
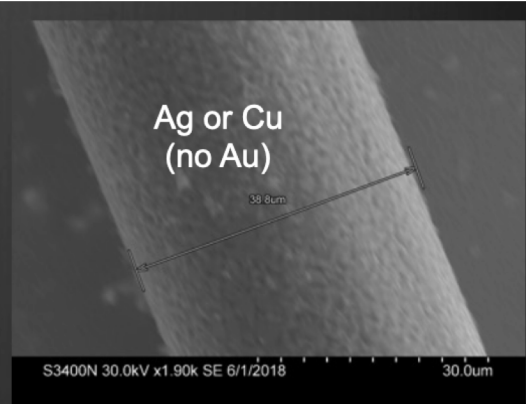


G. Charles et al.

Grancagnolo et al. (INFN)

High-power impulse magnetron sputtering (HiPIMS)

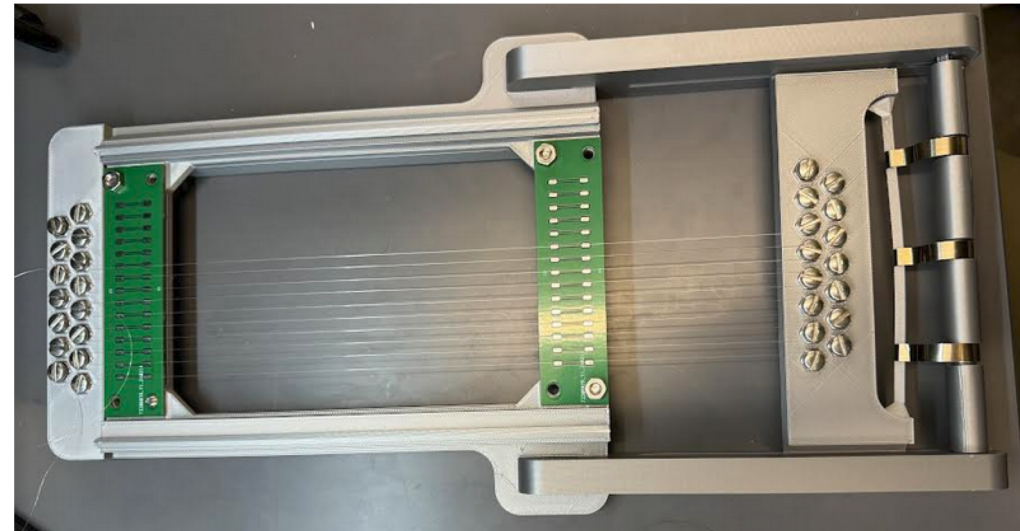
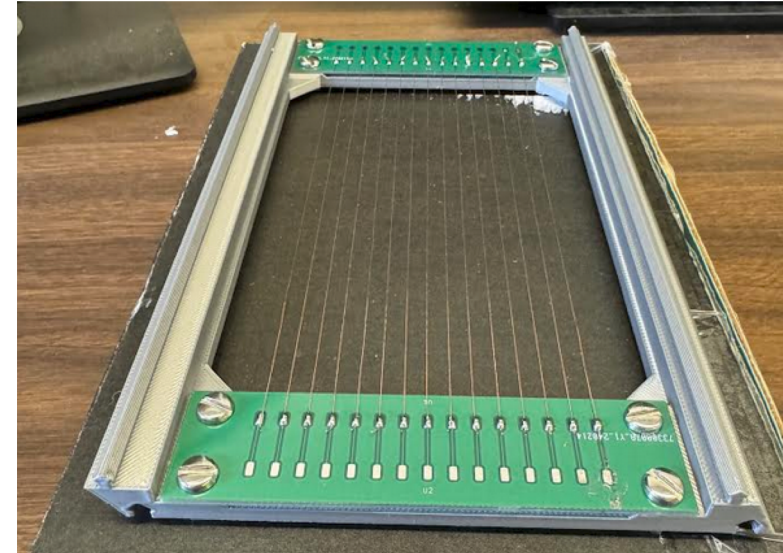
physical vapor deposition of thin films based on magnetron sputter deposition (extremely high power densities of the order of kW/cm² in short pulses of tens of μs at low duty cycle <10%)



- Purdue is using 30 um diameter Dexmat carbon sense wires
- Purdue benchmark is 25 um diameter tungsten wire from Midwest Tungsten
- Metal coating is a future project
 - Purdue has infrastructure
 - Atomic Layer Deposition (ALD)
 - Chemical Vapor Deposition (CVD)
 - Plasma Enhanced Chemical Vapor Deposition (PECVD)
 - High Density Plasma CVD (HDPCVD)
 - E-beam Evaporation DC/RF Sputtering multi-deposition (E-Beam Evaporation + Sputtering)
 - GaN Molecular Beam Epitaxy (MBE)
 - PVD Pulsed Laser Deposition (PLD)
 - Electrodeposition

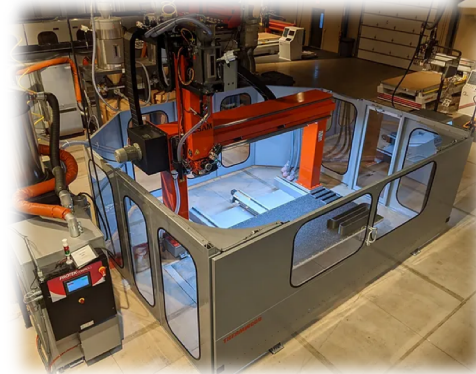


- Printed Circuit boards control the location of each wire
- Chamber is built in layers that can be stacked and offset for alternating sense and cathode wires
- Tension is applied using constant force springs and screws on a carriage
- Next steps: Sealed source & record data & spectra
- Stay tuned...



EPIC specific Mechanics workshop at Purdue

- Aimed specifically at Mechanics
- <https://indico.cern.ch/event/1336746/page/3>
[2301-satellite-events](#)
- Potential topics
 - Subdetector mechanics
 - Global mechanics
 - Integration & Assembly
 - Service & Mass optimization
- Ahead of the forum for tracking detectors,
Tuesday 28th May:
<https://indico.cern.ch/e/ftdm24>
- 2nd Bulletin to come today



Exchange of ideas & progress across existing collaborations:

- Snowmass process, ~~but no dedicated forum in the US to exchange on this~~
 - **CPAD RDC 10 “Detector Mechanics R&D”** <https://cpad-dpf.org>

FTDM workshop

- Forum on Tracking Detector Mechanics @Purdue
 - Registration Fee's likely around ~250\$ / person
 - FTDM 2024, May 29th – 31st
 - 3 days at Purdue
 - Tours of Silicon & Composite labs @Purdue
 - Poster Session & Industry sponsors

Satellite events

- Satellite event on May 28th focus on EPIC:
- Half-day on Friday devoted 1st RDC10 collaboration meeting, 31st May

<https://indico.cern.ch/event/1336746/>

Forum on Tracking Detector Mechanics 2024

Purdue University, West Lafayette, USA
29-31 May 2024

- Mechanics
- Materials
- Thermal Management
- Simulation Tools
- System Management
- Environmental Control

Satellite events

- EIC Mechanics Workshop 28 May
- Mechanics R & D Session 31 May

Organizing Committee:
Eric Anderssen, Corrado Gargiulo, Andreas Jung, Carlos Marinas, Andreas Mussgiller, Antti Onnela, Marco Oriunno, Paolo Petagna, Burkhard Schmidt, Sandro Tomassini, Bart Verlaat, Georg Viehhauser.

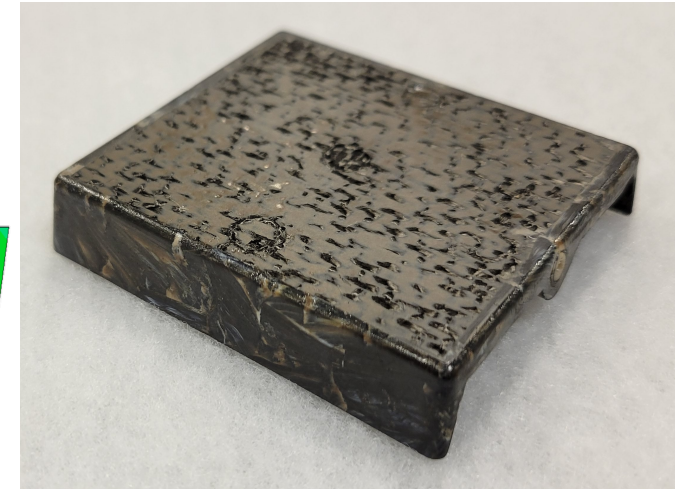
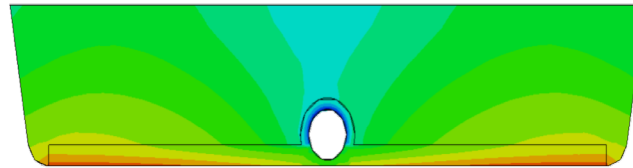
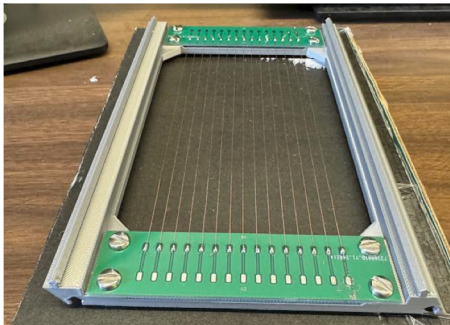
Local Organizers:
Benjamin Denos, Sushrut Karmarkar, Kristin Deweese.

Contact & Information
ftdm2024@purdue.edu
<https://indico.cern.ch/e/ftdm24>

PURDUE
UNIVERSITY

Detector mechanics can play a significant role in a detector's performance, improvements require:

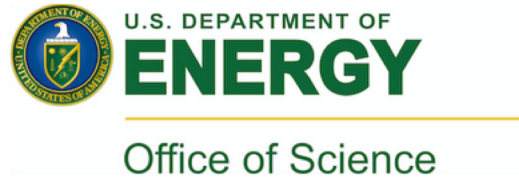
- In-depth study of total mass folded w thermal performance
- Novel ways to reduce the total mass



Detector Mechanics R&D

- First prototypes w improved performance compared to current state-of-the-art tracker mechanics
- Applicable also to calorimetry, TOF, other systems
- Next steps: Pressure test and connections to form a larger structure
- Snowmass white paper: <https://arxiv.org/abs/2203.14347>

This research is supported by:



Composite Manufacturing & Simulation Center (CMSC) at Purdue, completed in summer 2016

Purdue Center of Excellence across disciplines: Aeronautics, Chemical Eng, Materials Eng, Aviation Tech, Computer graphics, **and Physics**

A. Jung – Associated member of CMSC

Professional composite experience:

Seven full-time technical staff, five post-doctoral researchers, twenty grad's

35,000 sq. ft. of office and laboratory space

2 large pressurized ovens, 1 larger oven with vacuum hook-ups

Larger ovens accessible with industry partners

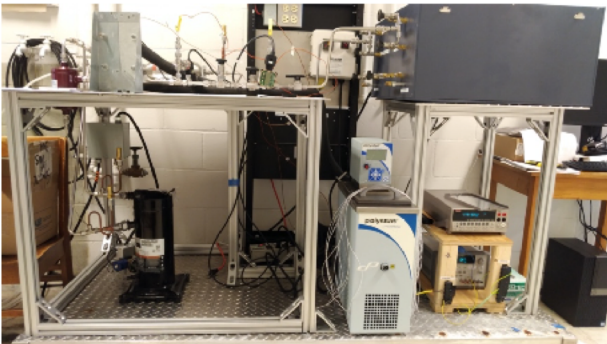


Cooling Technologies Research Center:

- Multi-disciplinary center to study micro-channels, fluid dynamics, cooling (air & fluid), thermal interface materials, etc.

Purdue Silicon Detector Laboratory:

- Large clean rooms for automated pixel module assembly & electronic tests
- Thermal conductivity setups, etc.



CTRC center:

<https://engineering.purdue.edu/CTRC/research/index.php>

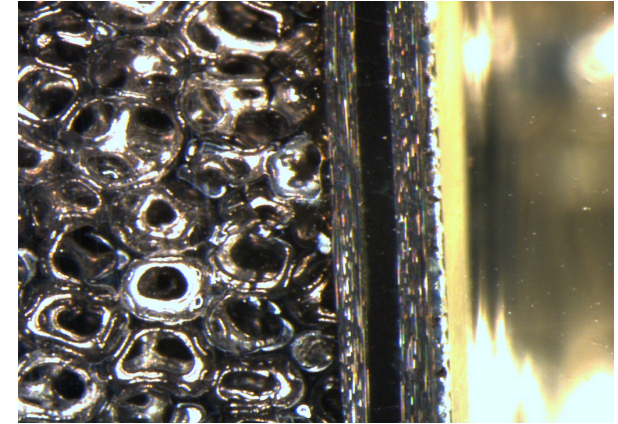
PSDL-CTRC Collaboration on:

- Various aspects of thermal management relevant for the applications at future collider
- Cooling box setup for thermal tests

Pixel support structures

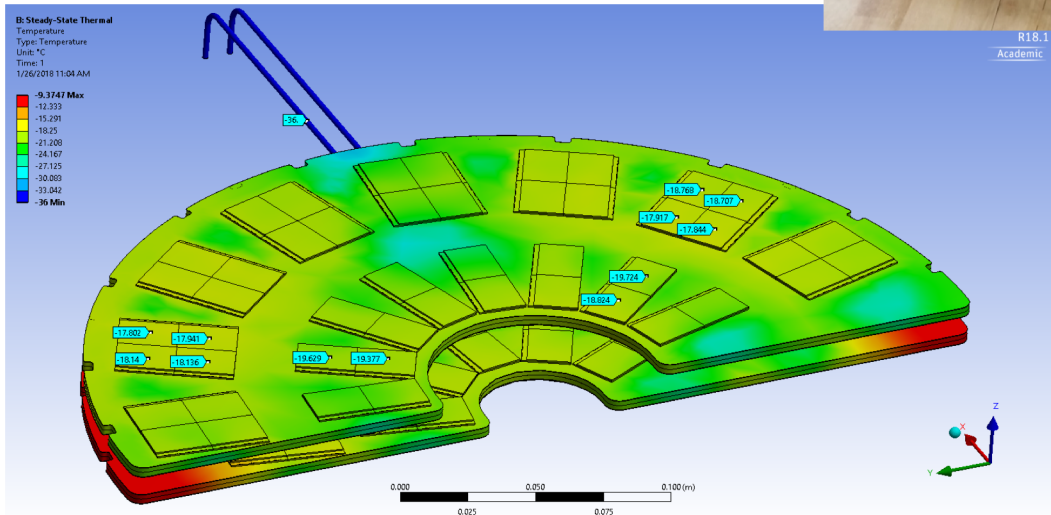
- Disc-like support structures made from Carbon Foam & Fiber
- FEAs use TC measurements as inputs
- Capable of cooling all ~1800 pixel modules
- Carbon is light-weight, and strong

1st half dee prototype, Cornell University

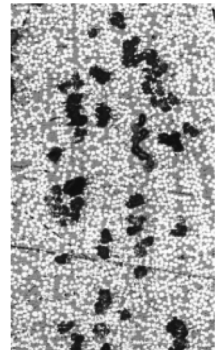


Carbon foam

3-ply skin



Bad laminate



High TC support pieces

- Use simulation and prediction based on material characterization to ensure accurate prediction of final part performance
- Applied to CMS structures already with full chain of tool compensation, machining, cure and load test
- Minimize material budgets and optimize thermal performance

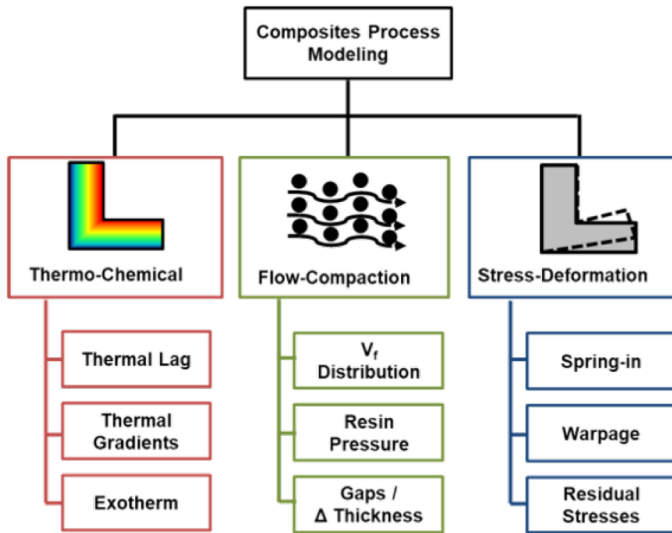
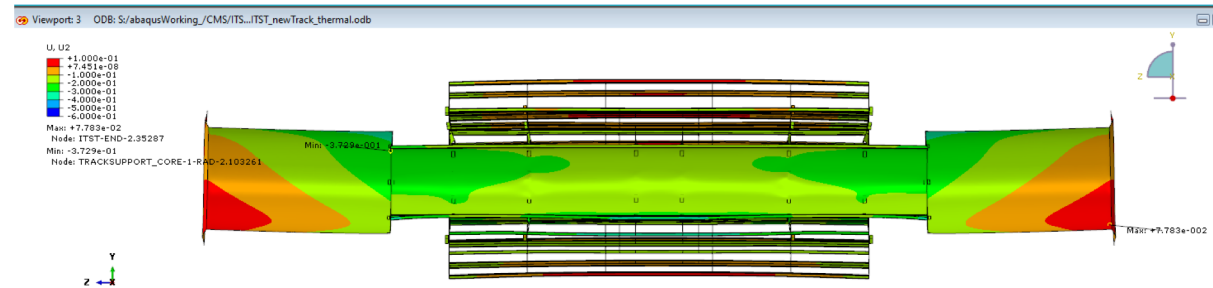
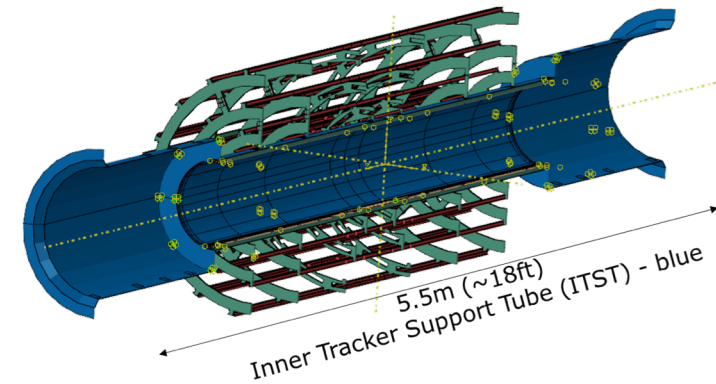
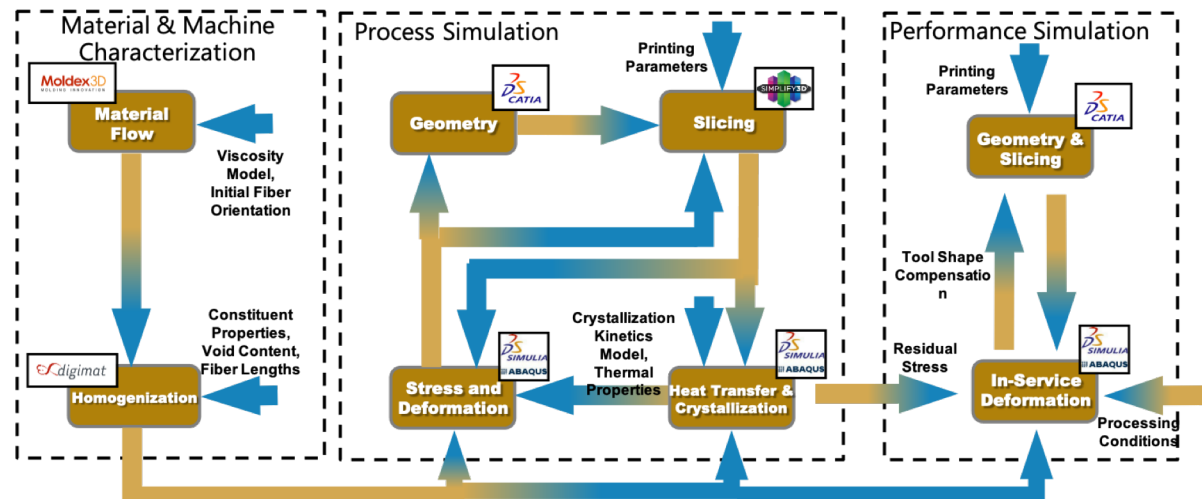
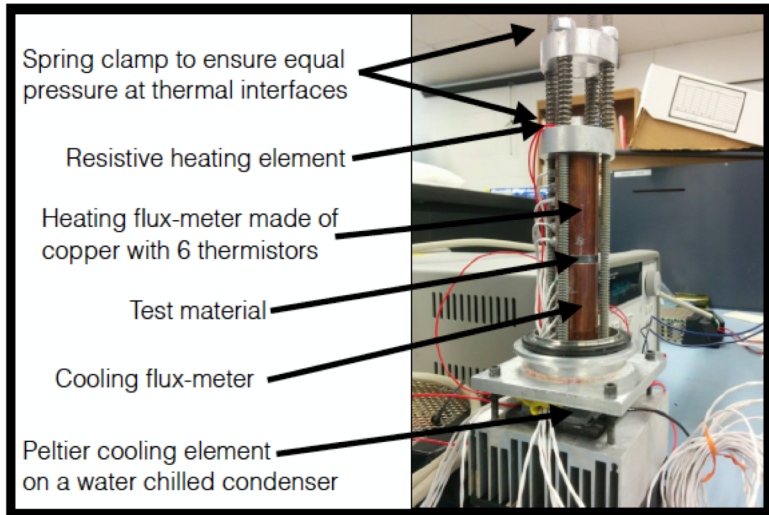


Figure 1-1 Composites process modeling problem types

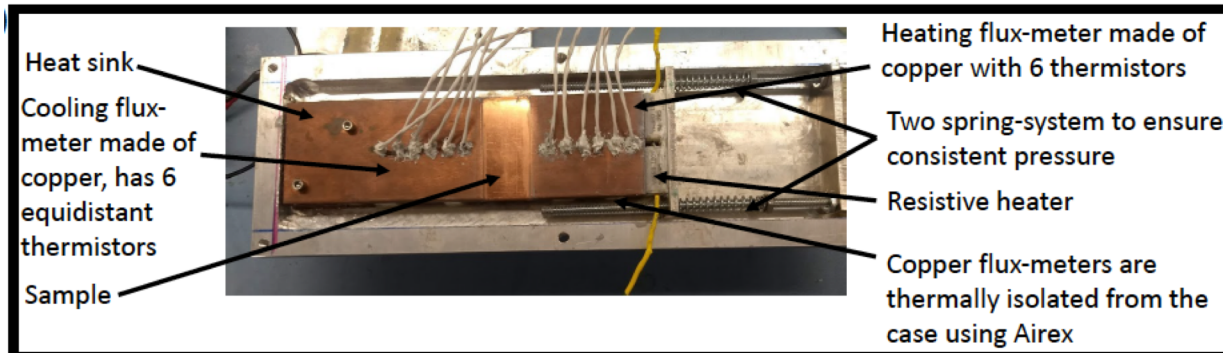
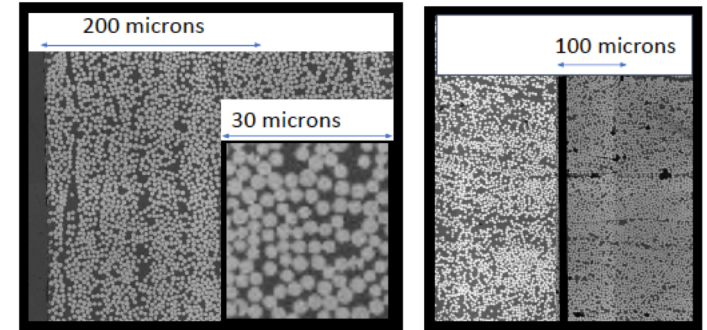


Thermal conductivities

- UG student driven activities, low-cost but precise
- High pressure curing to boost TC, factor 2 improvement
- Additional fillers to boost TC while maintaining mechanical strength
- Method & Results to be submitted to JINST soon...



- High pressure samples increase volume fraction to 72%
- Microscopies to measure volume fractions



| Sample/ Direction of measurement | Thermal conductivity (<i>k</i>) [W/mK] | Interface thermal resistance of Flux-meter-TIM-Sample (<i>R_{int}</i>) [Km ² /W] | Reduced χ^2 of the linear fit | Expected value of <i>k</i> [W/mK] |
|---|--|---|--|--------------------------------------|
| K13C2U+EX1515 carbon fiber composite (Unidirectional) | | | | |
| x-axis | (320 ± 28) | (1.8 ± 0.4) · 10 ⁻⁵ | 0.83 | 318 [3] |
| y-axis | (6.0 ± 2.6) | (3.8 ± 2.8) · 10 ⁻⁴ | 0.17 | 0.53 [3] |
| z-axis | (1.09 ± 0.15) | (-6.0 ± 17.0) · 10 ⁻⁵ | 0.05 | 0.53 [3] |
| z-axis (20 bar) | (2.21 ± 0.31) | (3.0 ± 7.0) · 10 ⁻⁵ | 0.09 | 1.2 [3] |
| K13D2U+EX1515 carbon fiber composite (Unidirectional) | | | | |
| x-axis | (376 ± 31) | (1.7 ± 0.3) · 10 ⁻⁵ | 0.65 | 410 [3] |
| y-axis | (7.5 ± 4.4) | (3.9 ± 3.5) · 10 ⁻⁴ | 0.01 | 0.53 [3] |
| z-axis | (1.44 ± 0.24) | (1.4 ± 1.4) · 10 ⁻⁴ | 0.44 | 0.53 [3] |
| z-axis (20 bar) | (2.79 ± 0.46) | (2.0 ± 9.0) · 10 ⁻⁵ | 0.43 | 1.2 [3] |
| Other materials | | | | |
| IM7 8552 (x-axis) | (8.0 ± 2.3) | (1.2 ± 0.8) · 10 ⁻⁴ | 0.85 | 5.50 [20] |
| Celstran® PPS-CF50-01 (z-axis) | (0.34 ± 0.08) | (-2.2 ± 4.6) · 10 ⁻⁴ | 1.09 | 0.39 [21] |